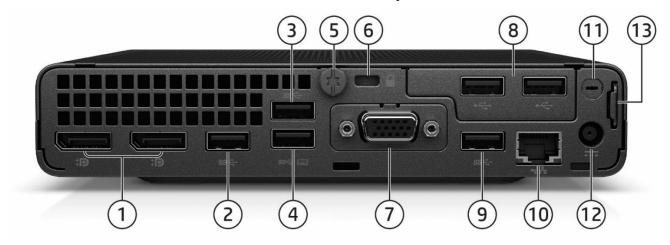
## HP EliteDesk 800 G8 Desktop Mini PC



- 1. Type-C® SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port
- 3. Type-A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/1.5A)
- 4. Combo Audio Jack with CTIA and OMTP headset support
- 5. Dual-state power button
- 6. Hard drive activity light



## HP EliteDesk 800 G8 Desktop Mini PC



- (2) Dual-Mode DisplayPort™ 1.4 (DP++)
- Type-A SuperSpeed USB 5Gbps signaling rate port
- Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 5. Cover release thumbscrew
- 6. Standard cable lock slot (10 mm)
- 7. (1) Flex Port 1, choice of:
  - HDMI 2.0b
- Fiber NIC (100Mbps and 1Gbps)<sup>1</sup>
- VGA
- Serial<sup>2</sup>
- DisplayPort<sup>™</sup> 1.4
   Thunderbolt 3<sup>1</sup>
- Type-C<sup>™</sup> SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort<sup>™</sup> Alt Mode and 100W Power Intake
- Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)
- Dual Type A SuperSpeed USB 5Gbps signaling rate port

- 8. (1) Flex Port 2, choice of:
  - VR Ready NVIDIA GTX 1660 Ti discrete GPU
  - Dual Type-A Hi-Speed USB 480Mbps signaling rate port
  - Serial
  - Second external antenna
- 9. Type-A SuperSpeed USB 10Gbps signaling rate port
- 10. RJ45 network connector
- 11. External WLAN antenna opening
- 12. Power connector
- 13. Retractable Padlock loop

#### **Not Shown**

Slots (1) Internal M.2 2230 connector for WLAN

(2) Internal M.2 SSD storage 2280 connector

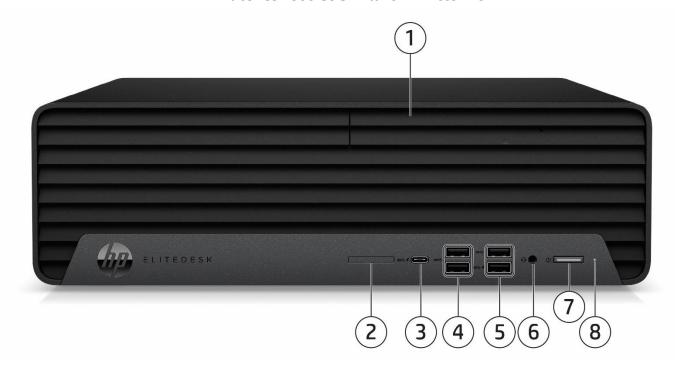
Bays (1) 2.5- inch SATA drive Bay (not available on discrete graphics sku)

Mounting Support for

- VESA Sleeve Standalone
  Quick Release Bracket
  B300/B500 Mounting bra
- B300/B500 Mounting bracket
   Integrated Work Center Stand
- 1. Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected Europe countries and Korea.
- 2. Sold separately or as an optional feature.



### **HP EliteDesk 800 G8 Small Form Factor PC**

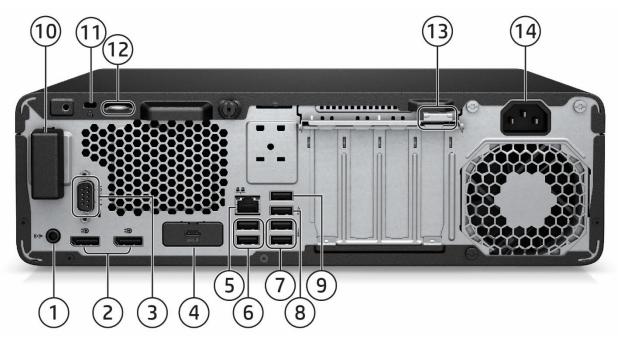


- 1. Slim optical drive (optional)
- 2. SD 4 Card Reader (optional)
- 3. Type-C<sup>®</sup> SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 4. (2) Type A SuperSpeed USB 10Gbps signaling rate port
- 5. (2) Type A SuperSpeed USB 5Gbps signaling rate port (1 with charge support up to 5V/1.5A)
- 6. Combo Audio Jack with CTIA and OMTP headset support
- 7. Dual-state power button
- 8. Hard drive activity light

### **Not Shown**

- (2) PCI Express x16 graphics connectors (one wired as x4)
- (2) PCI Express x1
- (3) M.2 (1 as M.2 2230 socket for WLAN/BT and 2 as M.2 2280 socket for storage)

### **HP EliteDesk 800 G8 Small Form Factor PC**



- 1. Audio line-out connector
- 2. (2) Dual-Mode DisplayPort™ 1.4a (DP++)
- 3. Optional Serial port (shown here installed)
- 4. Optional port, choice of (shown here USB-C® installed):
  - DisplavPort™
- Serial
- HDMI 2.0b
- VGA
- Dual Type-A SuperSpeed USB 5Gbps signaling rate port
- USB-C® SuperSpeed 10Gbps signaling rate port (Alt Mode DP 1.4 with 15W output)
- 5. RJ45 network connector
- 6. (2) Type A Hi-Speed USB 480 Mbps signaling rate port with 13. wake from S4/S5
- 7. (2) Type A SuperSpeed USB 10Gbps signaling rate port

- 8. (1) Type A SuperSpeed USB 5Gbps signaling rate port
- 9. (1) Type A Hi-Speed USB 480 Mbps signaling rate port
- Internal WLAN antenna cover (optional, shown here not installed)
- 11. Standard cable lock slot
- 12. Intrusion sensor/hood lock (optional, shown here not installed)
- 13. Integrated keyboard/mouse wire hoop
- 14. Power cord connector
- 12. Intrusion sensor/hood lock (optional, shown here not installed)
  - Integrated keyboard/mouse wire hoop
- 14. Power cord connector

### **Not shown**

### **Optional Ports**

Thunderbolt™ 3 port card<sup>1</sup>

PS/2 & serial port card (connected to the mainboard via a flyer cable)<sup>1</sup>

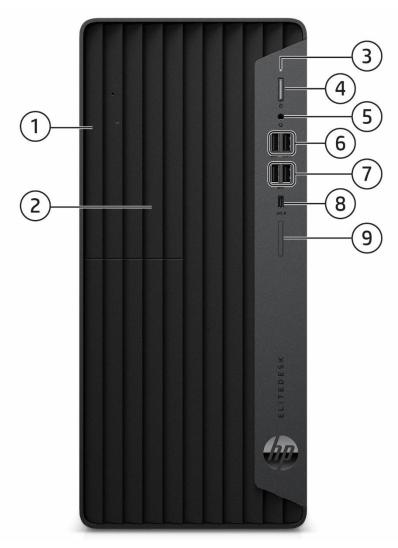
Parallel port1

1. Each of the legacy port options would occupy one rear slot.

#### **Bays**

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5" with Caddy)
- (1) 9.5 mm slim optical drive bay

### **HP EliteDesk 800 G8 Tower PC**



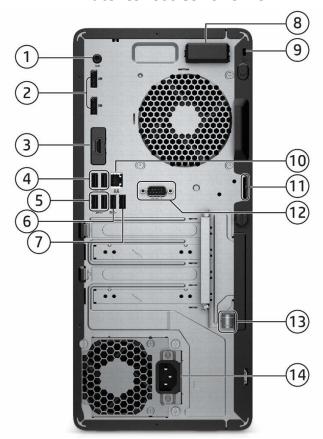
- 1. Slim optical drive (optional)
- 2. External 5.25-inch Half-Height Drive Bay (optional)
- 3. Hard drive activity light
- 4. Dual-state power button
- 5. Combo Audio Jack with CTIA and OMTP headset support
- **Not Shown**

### **Slots**

(2) PCI Express x16 graphics connectors (one wired as x4) (3) M.2 (1 as M.2 2230 socket for WLAN/BT and 2 as M.2 2280 socket for storage)

- 6. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
- 7. (2) Type A SuperSpeed USB 5Gbps signaling rate port (1 with charge support up to 5V/1.5A)
- 8. Type-C® SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 9. SD card 4.0 reader (optional)
  - (2) Type-A SuperSpeed USB 10Gbps signaling rate port

### **HP EliteDesk 800 G8 Tower PC**



- Audio line-out jack connector 1.
- (2) Dual-Mode DisplayPort™ 1.4 (DP++) 2.
- Flex port, choice of (shown here HDMI installed): 3.
  - DisplayPort™ 1.4

  - HDMI 2.0b
  - VGA
- Dual Type-A SuperSpeed USB
  - 5Gbps signaling rate port
- USB-C® SuperSpeed USB 10Gbps signaling rate port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)

Serial

(2) Type A Hi-Speed USB 480 Mbps signaling rate port with 13. Integrated keyboard/mouse wire hoop wake from \$4/\$5

- (2) Type A SuperSpeed USB 10Gbps signaling rate port 5.
- (1) Type A SuperSpeed USB 5Gbps signaling rate port 6.
- 7. (1) Type A Hi-Speed USB 480 Mbps signaling rate port
- 8. Internal WLAN antenna (optional, shown here installed)
- 9. Standard cable lock slot
- 10. RJ-45 (network) jack
- 11. Intrusion sensor/hood lock (optional, shown here not installed)
- 12. Serial port (optional, shown here not installed)
- 14. Power cord connector

### Not shown **Optional ports**

Thunderbolt<sup>™</sup> 3 card<sup>1</sup>

PS/2 & serial port card (connected to mainboard via a flyer cable) 1

Parallel Port1

1. Each of the legacy options will occupy one rear slot.

## Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay



## HP EliteOne 800 G8 24 & 27 All-in-One PC Touch/Non-Touch

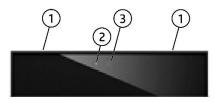


1. Camera (optional)

2. Speakers (optional)

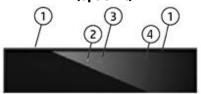
## HP EliteOne 800 G8 24 & 27 All-in-One PC Touch/Non-Touch

### 5MP Pop-up Webcam (optional)



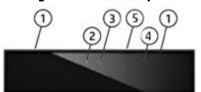
- 1. Dual Microphones
  - 2. Webcam Light
  - 3. SMP Webcam

## 5MP Pop-up Webcam +IR Sensor (optional)



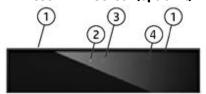
- 1. Dual Microphones
  - 2. Webcam Light
- 3. IR/5MP Webcam 4. IR Light

## 5MP Pop-up Webcam +IR Sensor + Time of Flight Sensor (TOF) (optional)



- 1. Dual Microphones
  - 2. Webcam Light
- 3. IR/5MP Webcam 4. IR Light
  - 5. TOF Sensor

Dual Facing 5MP Pop-up Webcam Webcam +IR Sensor (optional)



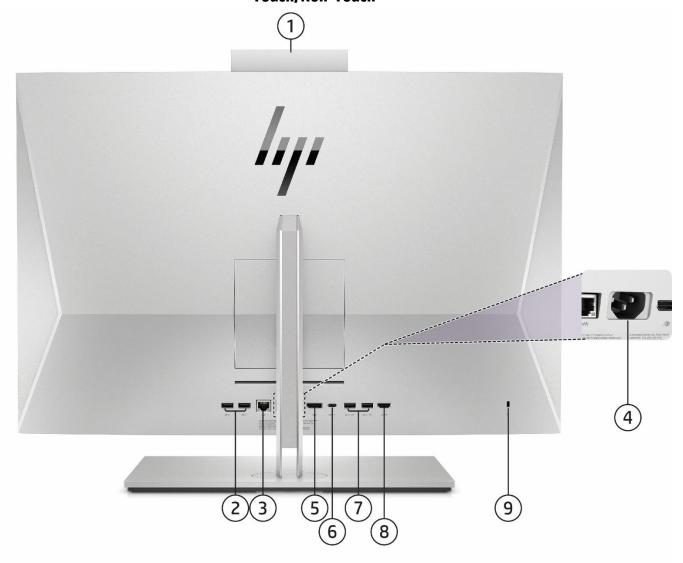
- 1. Dual Microphones
  - 2. Webcam Light
- 3. IR/5MP Webcam
  - 4. IR Light

## HP EliteOne 800 G8 24 & 27 All-in-One PC Touch/Non-Touch



- 1. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 3. Combo Audio Jack with CTIA and OMTP headset Support

## HP EliteOne 800 G8 24 & 27 All-in-One PC Touch/Non-Touch

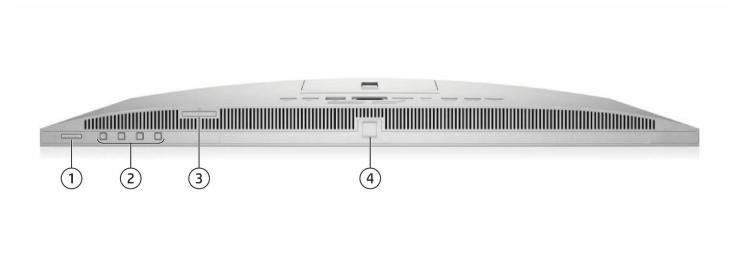


### **Rear components and rear ports**

- 1. Camera (optional)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
- 3. RJ-45 network connector/jack
- 4. Power Connector
- Dual-Mode DisplayPort™1.4 (DP++)

- Type-C<sup>®</sup> SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 7. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
- 8. HDMI-in 2.0a connector
- 9. Standard cable lock slot

## HP EliteOne 800 G8 24 & 27 All-in-One PC Touch/Non-Touch



- 1. Dual-State Power button
- 2. OSD control buttons
- 3. SD card reader 4.0 (optional)

### **Bottom**

- 3. SD card reader 4.0 (optional)
- 4. Fingerprint Sensor (optional)

### Not shown

### **Slots**

## (1) internal M.2 PCIe x1 connector for optional wireless NIC

(2) internal M.2 PCIe x4 connector for optional m.2 SSD

### **VESA**

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)





#### AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- Intel® Q570 chipset supporting Intel® 11<sup>th</sup> generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro® Technology (available with Core i5-11500 and above processors) <sup>1,2</sup>
- Support for three (3) M.2 Storage slots (All-in-One)
- Intel® Optane™ Memory H10 with Solid State Storage
- Intel® UHD graphics with optional discrete graphics configure systems to up to 7 monitors (TWR, SFF and DM 35W Processors only)
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6 + BT5.1 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 3200 MT/s)
- Support for up to 7 monitors via two standard DisplayPort™ 1.4 ports, a configurable Flex I/O port for video options and a
  discrete graphics card on TWRs, SFFs and DMs. All-in-One supports up to two additional monitors via DisplayPort™ or
  Type-C® USB in alternate mode.
- Configurable FlexPort which provides the following choices: HDMI 2.0b, Serial, VGA, DisplayPort™ 1.4, or USB Type-C® with DisplayPort™ 1.4 (USB Type-C® with DisplayPort™ 1.4 with Power Delivery [PD] on DMs), Thunderbolt 3 (PCIe card on TWR, SFF), Thunderbolt 3 with USB4.0 (port on DM and will be ready in post launch), and Dual USB Type-A for (TWRs, SFFs and DMs). See Ports section for port availability by platform. FlexPort not supported on All-in-One.
- 2<sup>nd</sup> FlexPort available for configuration on the HP EliteDesk G8 Desktop Minis with the following ports: mini-DisplayPorts and micro-HDMI (when configured with discrete graphic card), Serial, Dual USB Type-A, and 2<sup>nd</sup> external antenna.
- Configurable NVIDIA® GeForce®VR ready discrete graphics card with (3) mini-DisplayPorts and (1) micro-HDMI video port for DM³ to support up to (7) monitors with minimum 4K resolution and option to connect up to (3) monitors with 5K resolution via graphics card.
- Configurable AMD® Radeon, NVIDIA® GeForce® and NVIDIA® Quadro® VR ready discrete graphics on TWR 3
- Compatibility with HP Mini-In-One 24 Display (800 G8 DM with 100W USB-C +PD option card)
- Compatible with HP Reverb G2 VR Headset (TWR, DM)
- Models can be configured with multiple data drives in a RAID array
- Audio by Bang & Olufsen (All-in-One)
- Integrated Low Blue Light Panels on All-in-One (excludes 23.8" Touch Models)
- Enhanced Security with HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.
- CCC, CECP and SEPA Certified (TWR/SFF/DM/All-in-One)
- TCO Edge for All-in-One
- TCO (TWR/SFF/DM)
- PC chassis and all internal components and modules are manufactured with low halogen content<sup>4</sup>
- Dust filter available for following platforms (DM with 35W processor, SFFs and TWR)
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain
  restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No.62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)
- 1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 2. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3<sup>rd</sup> party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3<sup>rd</sup> party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.
- 3. VR-ready as optional feature, specific configuration to support: 800 TWR: Nvidia GeForce 3070 card;800 DM: Nvidia GTX 1660Ti card.
- 4. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.





### NOTE: See important legal disclosures for all listed specs in their respective feature sections

### **PRODUCT NAME**

HP EliteDesk 800 G8 Tower PC

HP EliteDesk 800 G8 Small Form Factor PC

HP EliteDesk 800 G8 Desktop Mini PC

HP EliteOne 800 G8 24 All-in-One PC

HP EliteOne 800 G8 27 All-in-One PC

#### **OPERATING SYSTEM**

Preinstalled Windows 10 Pro 64 - HP recommends Windows 10 Pro for business<sup>1</sup>

Windows 10 Pro 64 (National Academic only)2

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)1

**FreeDOS** 

Web-supported only Windows10 Enterprise 64 (Web Support)<sup>1</sup>

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply, and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

**NOTE:** Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7<sup>th</sup> generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282.

#### **Supported Versions**

HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.

#### **CHIPSET**

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Q570	<u>x</u>	<u>x</u>	<u>x</u>	<u>x</u>





### **PROCESSORS**

Intel® 11 <sup>th</sup> Generation Core™ Processors	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i9-11900 Processor with Intel® UHD Graphics 750 (2.5GHz, up to 5.2 GHz with Intel® Turbo Boost Technology¹, 16MB cache, 8 cores) 65W <sup>2.3</sup> Supports Intel® vPro® Technology⁴		х	х	x
Intel® Core™ i9-11900T Processor with Intel® UHD Graphics 750 (1.5GHz, up to 4.9GHz with Intel® Turbo Boost Technology¹, 16MB cache, 8 cores) 35W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	х			
Intel® Core™ i7-11700 processor with Intel® UHD Graphics 750 (2.5 GHz, up to 4.9 GHz with Intel® Turbo Boost Technology¹, 16 MB cache, 8 cores) 65W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	х	х	х	х
Intel® Core™ i7-11700T Processor with Intel® UHD Graphics 750 (1.4 GHz, up to 4.6 GHz with Intel® Turbo Boost Technology¹,16MB cache, 8 cores) 35W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	х			
Intel® Core™ i5-11600 processor with Intel® UHD Graphics750 (2.8 GHz, up to 4.8 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 65W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	Х	х	х	x
Intel® Core™ i5-11600T processor with Intel® UHD Graphics 750 (1.7GHz, up to 4.1 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 35W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	х			
Intel® Core™ i5-11500 processor with Intel® UHD Graphics 750 (2.7GHz, up to 4.6 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 65W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	Х	х	х	х
Intel® Core™ i5-11500T processor with Intel® UHD Graphics 750 (1.5GHz, up to 3.9 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 35W <sup>2.3</sup> Supports Intel® vPro® Technology⁴	х			
Intel® Core™ i5-11400 processor with Intel® UHD Graphics 730 (2.6 GHz, up to 4.4 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 65W <sup>2.3</sup>	Х	Х	X	X
Intel® Core™ i5-11400T processor with Intel® UHD Graphics 730 (1.3GHz, up to 3.7 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 6 cores) 35W <sup>2.3</sup>	х			

<sup>1.</sup> Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.



<sup>2.</sup> Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a configuration measurement of higher performance.

<sup>3.</sup> Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

<sup>4.</sup> For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro.



### **GRAPHICS**

Integrated Intel® Graphics	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® UHD Graphics 750 (integrated in 11 <sup>th</sup> gen Core i9/i7/i5-11500 and above)	X	Х	х	Х
Intel® UHD Graphics 730 (integrated in 11 <sup>th</sup> gen Core i5-11400 & i5-11400T)	Х	х	X	х

Optional Discrete Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 3070 8GB FH 3DP+HDMI Graphics Card <sup>1</sup>			Х	
NVIDIA® Quadro P2200 5GB 4DP Graphics Card			Х	
NVIDIA® Quadro P1000 4GB 4mDP Graphics Card			Х	
NVIDIA® Quadro P620 2GB 4mDP Graphics Card		X	X	
NVIDIA® Quadro P400 2GB w/ 2mDP to DVI Graphics Card		X	Х	
NVIDIA® Quadro P400 2GB w/ 2mDP to DP Graphics Card		X	Х	
NVIDIA® GeForce® GTX 1660Ti 6GB 1m HMDI, 3m DP Graphics Card²	X			
AMD® Radeon™ RX 5300 3GB NGC Graphics Card				
AMD® Radeon™ RX 550X 4GB FH DP+HDMI Graphics Card¹		X	Х	
AMD® Radeon™ R7 430 2GB DP+VGA³		X	Х	
AMD® Radeon™ R7 430 2GB 2DP <sup>3</sup>		X	Х	

<sup>1.</sup> Requires 550W chassis

**NOTE:** The TWR can support a single discrete graphics card up to 300W with a 550W Power Supply.

pters and Cables	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
HP DisplayPort™ Cable	Х	X	X	Х
HP DisplayPort™ to DVI-D Adapter	Х	X	X	Х
HP DisplayPort™ to HDMI True 4K Adapter	Х	X	Х	Х
HP DisplayPort™ to VGA Adapter	Х	X	X	Х
HP USB to Serial Port Adapter	Х	X	X	Х
HP USB-C® to HDMI 4K Adapter		X	X	X
HP USB-C® to DisplayPort Adapter				Х
HP DVI Cable				Х
HP HDMI Standard Cable Kit (HDMI)				Х
50cm USB-C Cable (100W power delivery)	Х			

<sup>2.</sup> Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro —HDMI 2.0 port in order to drive up to 7 displays directly on the Desktop Mini.

<sup>3.</sup> Not available in all regions



### **STORAGE**

3.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 3.5in SATA HDD		X	X	
1TB 7200RPM 3.5in SATA HDD		X	X	
2TB 7200RPM 3.5in SATA HDD		Х	Х	

2.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB 7200RPM 2.5in SATA HDD	X	Х	Х	
1TB 7200RPM 2.5in SATA HDD	X	X	Х	
2TB 5400RPM 2.5in SATA HDD	X	Х	Х	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	X	Х	X	
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	Х	Х	х	

<sup>\*</sup> Storage DriveLock does not work with Self Encrypting or Optane based storage

PCIe NMVe Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
256GB M.2 2280 PCIe NVMe SSD	Х	Х	X	Х
512GB M.2 2280 PCIe NVMe SSD	Х	Х	Х	Х
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD				
256GB M.2 2280 PCIe 3NVMe Three Layer Cell SSD	Х	X	X	Х
256GB M.2 2280 PCIe 4NVMe Three Layer Cell SSD	Х	X	X	Х
512GB M.2 2280 PCIe 3 NVMe Three Layer Cell SSD	Х	X	X	Х
512GB M.2 2280 PCIe 4 NVMe Three Layer Cell SSD	Х	X	X	Х
1TB M.2 2280 PCIe 3 NVMe Three Layer Cell SSD	Х	Х	X	Х
1TB M.2 2280 PCIe 4 NVMe Three Layer Cell SSD	Х	Х	X	Х
2TB M.2 2280 PCIe 3 NVMe Three Layer Cell SSD	Х	X	X	Х
2TB M.2 2280 PCIe 4NVMe Three Layer Cell SSD	X	X	X	Х
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	Х	Х	Х	Х
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	Х	Х	Х	Х
256GB Intel® Optane™ Memory H10 with Solid State Storage*,**	Х	X	X	Х
512GB Intel® Optane™ Memory H10 with Solid State Storage*,**	Х	X	Х	Х

**NOTE\*** Storage DriveLock does not work with Self Encrypting or Optane based storage.

**NOTE**\*\* Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.





Optical Disc Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive <sup>1</sup>		X	X	
HP 9.5mm Slim DVD Writer Drive <sup>1</sup>		Х	Х	

<sup>1.</sup> HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Media Card Reader	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		Х	Х	Х

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### **MEMORY**

Men	ory Type	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
	DDR4-3200, 64 GB, 2 SODIMM	X			X
	DDR4-3200 (Transfer rates up to 3200 MT/s), 64 GB, 4 DIMM		X		
	DDR4-3200 (Transfer rates up to 2933 MT/s), 128 GB, 4 DIMM		X	Х	

emory Configuration	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
4 GB (1 x 4 GB)	X	X	X	X
8 GB (2 x 4 GB)	X	X	X	X
8 GB (1 x 8 GB)	X	X	X	X
16 GB (2 x 8 GB)	X	X	X	X
16 GB (1 x 16 GB)	X	X	X	X
32 GB (2 x 16 GB)	X	X	X	X
32 GB (1 x 32 GB)	X	X	X	X
64 GB (2 x 32 GB)	X	X	X	X
128 GB (4 x 32 GB)		X	X	

NOTE: Memory modules support data transfer rates up to 3200 MT/s; actual data rate is determined by the system configured.

**NOTE:** When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different data transfer rates or memory rank mix within the same channel is not allowed.

**NOTE:** All memory slots are customer accessible / upgradeable.

**NOTE:** For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.





### **NETWORKING/COMMUNICATIONS**

Ethernet (RJ-45)	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® I219-LM 1 Gigabit Network Connection LOM (vPro)	Х	Х	X	Х
Intel® I225-T1 2.5 Gigabit Network Connection LOM (optional)	Х	Х	Х	

Nireless <sup>1</sup>	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Wi-Fi 6 AX201 + BT5.1 (802.11AX 2x2 vPro, supporting gigabit data rate²)	х	х	Х	Х
Intel® Wi-Fi 6 AX201 + BT5.1 (802.11AX 2x2 non-vPro, supporting gigabit data rate²)	х	х	Х	
Realtek RTL8852AE 802.11ax 2x2 Wi-Fi® 6 + BT5.2	X	X	X	
Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + BT5				Х

<sup>1.</sup> Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

### **KEYBOARDS AND POINTING DEVICES**

Keyboards	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP USB 320K Keyboard	Х	X	X	X
HP USB Business Slim Wired SmartCard CCID Keyboard	Х	X	X	X
HP Business Slim PS/2 Wired Keyboard		X	Х	
HP 125 Wired Keyboard	Х	X	X	X
HP 125 AntiMic USB Wired Keyboard <sup>1</sup>	Х	X	Х	X
HP USB PS/2 Washable Wired Keyboard	х	Х	Х	X

Keyboard and Mouse Combo	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wireless Keyboard and Mouse Business Slim Keyboard	X	X	Х	X
HP USB Wired Keyboard and Mouse Premium Keyboard	oard and Mouse Premium Keyboard X X X			Х
HP Wireless Keyboard and Mouse Premium Keyboard	X	Х	Х	Х

se	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired 320M Mouse	X	X	Х	Х
HP PS/2 Mouse		X	Х	
HP USB Fingerprint Reader Wired Mouse	X	X	Х	X
HP USB PS/2 Washable Wired Mouse	X	X	Х	Х
HP Wired 125 Mouse	X	X	Х	X
HP Wired 128 Laser Mouse	X	X	Х	Х
HP Wired 125 Antimicrobial Mouse	X	X	Х	X

<sup>1.</sup> Availability may vary by country



<sup>2.</sup> Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

**Features** 

### **SECURITY**

	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	х	х	х	X
Solenoid Lock & Intrusion Sensor (optional)		X	Х	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			X
Support for chassis cable lock devices	X (10 mm barrel or smaller)	х	x	x
Support for chassis padlocks devices	X	X	X	
HP Fingerprint Sensor (optional)				Х
SATA port disablement (via BIOS)	X	X	X	
Serial, USB enable / disable (via BIOS)	X	X	X	X
Serial, parallel, USB enable / disable (via BIOS)	X	X	X	Х
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	X	X
Removable media write/boot control	X	X	X	Х
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	X	X	X	X



**Features** 

### **PORTS**

Ports – Internal Ports	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
PCI Express 4.0 x16		1	1	N/A
PCI Express 3.0 x16				
PCI Express 3.0 x16 (wired as x4)		1	1	
PCI Express 3.0 x4				
PCI Express 3.0 x1		2	2	
SATA port		4	4	N/A
Internal SATA storage connector	1			N/A
M.2 PCIe	(1) M.2 PCle3 x1 2230 (for WLAN) (1) M.2 PCle4 x4 2280 (for storage) (1) M.2 PCle3 x4 2280 (for storage)	(1) M.2 PCIe 3 x1 2230 (for WLAN) (1) M.2 PCIe 4 x4 2280 (for storage) (1) M.2 PCIe 3 x4 2280 (for storage) <sup>1</sup>	(1) M.2 PCIe 3 x4 2280 (for storage) <sup>1</sup>	(1) M.2 2230/2280 for WLAN (2) M.2 2280 for NVMe SSD One Attached to CPU PCIe Gen 4.0 Two attached to PCH PCIe Gen 3.0

1. M.2 SSD attached to CPU is PCIe Gen 4, the other two M.2 are PCIe Gen 3. **NOTE**: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

ndard User Accessible Ports	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A Hi-Speed USB 480Mbps signaling rate port		3 (rear)	3(rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port	1 (front) 2 (rear)	2 (front,1 fast charging) 1 (rear)	2 (front, 1 fast charging) 1 (rear)	2 rear
Type-A SuperSpeed USB 10 Gbps signaling rate port	1 (front) 2 (rear)	2 (front) 2 (rear)	2 (front) 2 (rear)	2 rear 1 side
Type-C® SuperSpeed USB 10 signaling rate Gbps port				1 rear 1 side
Type-C® SuperSpeed USB 20Gbps signaling rate port	1 (front)	1 (front)	1 (front)	
Video	2 DisplayPort™ 1.4	2 DisplayPort™ 1.4	2 DisplayPort™ 1.4	1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and OMTP headset support (front)	1 Universal Audio Jack with CTIA and OMPT headset support (front); 1 Audio-Line out (rear)	1 Universal Audio Jack with CTIA and OMPT headset support (front); 1 Audio-Line out (rear)	1 CTIA/OMTP UAJ (side)



Flexible Port 1, choice of <u>one</u> of following	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Dual Type-A SuperSpeed USB 5 Gbps signaling rate port	1	1	1	
Type-C <sup>®</sup> SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W	1	1	
Thunderbolt™ 3 <sup>2</sup>	13	1	1	
Video	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0b <u>or</u> VGA	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0b <u>or</u> VGA	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0b <u>or</u> VGA	
Serial	13	1	1	
Fiber NIC Adapter	(1) 100Mbps NIC			
Fiber NIC Adapter	(1) 1 Gbps NIC			
RJ-45 Ethernet NIC	(1) 2.5GbE			

- 2. Occupies a PCIe slot on TWR/SFF. Available in Q3, 2021.
- 3. Sold separately or as an optional feature.

(1) Flexible Port 2, choice of $\underline{one}$ of the following:	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>AiO</u>
Type-A USB	2 Hi-Speed USB			
Serial	1			
Discrete Graphics	1			
2 <sup>nd</sup> External antenna	1			

**NOTE**: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Bays	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
5.25" Half Height (External)			1	
9mm Slim Optical Disc Drive (ODD)		1	1	
SD Card Reader		1	1	1
2.5" Internal Storage Drive	14	1	1	
3.5" Internal Storage Drive		2	2	

4. SATA 2.5" internal storage drive cannot be selected if, discrete graphic card is selected.





## **USB SPECIFICATION AND MARKETING NAME MAPPING TABLE**

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



### **Features**

### SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

#### BIOS

HP BIOSphere Gen61 HP Secure Erase<sup>2</sup> Absolute Persistence Module<sup>3</sup> HP Drive Lock & Automatic Drive Lock<sup>4</sup> **BIOS Update via Network** HP Wake on WLAN

#### Software

**HP Desktop Support Utilities** HP Connection Optimizer<sup>5</sup> HP Easy Clean<sup>6</sup> mvHP **HP Privacy Settings HP PC Hardware Diagnostics Touchpoint Customizer for Commercial HP Notifications** HP Presence Aware<sup>7</sup>

**HP Setup Integrated 00BE HP Support Assistant<sup>8</sup>** 

**HP Noise Cancellation Software** 

HP QuickDrop9 **HP WorkWell** 

Microsoft Defender

Buy Microsoft Office (sold separately)

HP Smart Support<sup>10</sup>

### **Manageability Features**

HP Driver Packs (download)11

HP Client Catalog (download)

HP Image Assistant (download)

HP Manageability Integration Kit for Microsoft System Center Configuration Management Gen4 (download)<sup>12</sup>

Ivanti Management Suite (download)<sup>13</sup>

HP Cloud Recoverv14

HP Client Management Script Library (download)

#### **Security Management**

HP Pro Security Edition (optional)15 HP Client Security Manager Gen7<sup>16</sup>

HP Sure Sense<sup>17</sup>

HP Sure Admin<sup>18</sup>

HP Sure Click<sup>19</sup>

HP Sure Start Gen6<sup>20</sup>

HP Sure Run Gen421

HP Sure Recover Gen4<sup>22</sup>

**HP Tamper Lock** 

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

- 1. HP BIOSphere Gen6 requires Windows 10 and is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.
- 2. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 3. Absolute agent is shipped turned off and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-



### **Features**

agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 4. Drive Lock is not supported on NVMe drives.
- 5. HP Connection Optimizer requires Windows 10.
- 6. Not available with PS/2 keyboard / mouse.
- 7. HP Presence Aware requires a proximity sensor that is available on select EliteBooks and requires Windows Hello for authentication.
- 8. HP Support Assistant requires Windows and Internet access.
- 9. HP Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 10. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
- 11. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 12. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 13. Ivanti Management Suite subscription required.
- 14. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.
- 15. HP Pro Security Edition is available preloaded on select HP PCs and includes HP Sure Click Pro and HP Sure Sense Pro. 3-year license required. The HP Pro Security Edition software is licensed under the license terms of the HP End User License Agreement (EULA) that can be found at: https://h30670.www3.hp.com/ecommerce/common/disclaimer.do#EN\_US as modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for thirty-six (36) months thereafter ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support." HP Pro Security Edition is optimized for the SMB environment and ships pre-configured manageability is optional. The HP Pro Security Edition supports a limited tool set that can be used by the HP Manageability Integration Kit which can be downloaded from http://www.hp.com/go/clientmanagement.

  16. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 17. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.
- 18. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 19. HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A\_SureClick for complete details.
- 20. HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.
- 21. HP Sure Run Gen4 is available on select HP PCs and requires Windows 10.
- 22. HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.



#### **ENVIRONMENTAL & INDUSTRY**

### **ENERGY STAR® certified models available**

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <a href="http://www.epeat.net">http://www.epeat.net</a> for more information.

Low halogen (chassis, all internal components and modules)1

TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

#### **UNIT ENVIRONMENT AND OPERATING CONDITIONS**

**General Unit Operating Guidelines** 

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
  is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)<sup>2</sup>

Non-operating: -22° to 149° F (-30° to 65° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

2. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.





HP	EliteDesk	800	Desktop	Mini	G8 ser	ies

HP EliteDesk 800 Desktop		ho process of hair	to the following approvals and an				
Eco-Label Certifications & declarations	be labeled with one or more of these marks:  • IT ECO declaration  • US ENERGY STAR®  • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT®						
	registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.						
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop.						
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz 100VAC						
Normal Operation (Short idle)	7.795 watt	7.923 watt	7.573 watt				
Normal Operation (Long idle)	6.931 watt	7.02 watt	6.746 watt				
Sleep	0.8199 watt	0.851 watt	0.7776 watt				
Off	0.6586 watt	0.672 watt	0.633 watt				
	not offer ENERGY STAR® certified con PC featuring a hard disk drive, a high o	A) ENERGY STAR® specifications figurations, then energy efficier efficiers ficiency power supply, and a M	for computers. If a model family does ncy data listed is for a typically configured licrosoft Windows® operating system.				
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz				
Normal Operation (Short idle)	26.58095 BTU/hr	27.01743 BTU/hr	25.82393 BTU/hr				
Normal Operation (Long idle)	23.63471 BTU/hr	23.9382 BTU/hr	23.00386 BTU/hr				
Sleep	2.795859 BTU/hr	2.90191 BTU/hr	2.651616 BTU/hr				
Off	2.245826 BTU/hr	2.29152 BTU/hr	2.15853 BTU/hr				
	<b>NOTE:</b> Heat dissipation is calculated bone hour.	ased on the measured watts, as	ssuming the service level is attained for				
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L <sub>WAd</sub> , bels)		Sound Pressure (L <sub>pAm</sub> , decibels)				
Typically Configured – Idle	2.7		17				
Fixed Disk – Random writes	2.7		17				
Longevity and Upgrading	This product can be upgraded, pos features and/or components cont						
	Spare parts are available through production.	out the warranty period and	or for up to "5" years after the end of				
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC						
	Batteries used in the product do n						
	Mercury greater the1ppm by weig						
	Cadmium greater than 20ppm by	weight					
	Battery size: CR2032 (coin cell)						
	Battery type: Lithium						





Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.					
	Electronic Equipment (WEEE)					
	Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking					
	•	oxic Enforcement Act of 1986).	Cathornia, Safe Drinking			
		AR® certified. EPEAT® 2019 registered where applicable. E	Based on US EPEAT®			
		according to IEEE 1680.1-2018 EPEAT®. EPEAT® status va				
		epeat.net for more information.	, ,			
	<ul> <li>Plastics pa</li> </ul>	rts weighing over 25 grams used in the product are marke	d per IS011469 and IS01043.			
		ct contains a minimum of 35% post-consumer recycled pla	astic (by wt.); Including 10%			
		post-consumer recycled plastic*				
	This production	ct is 95.1% recycle-able when properly disposed of at end	of life.			
	*NOTE: Recyc	led plastic content percentage is based on the definition set in th	e IEEE 1680.1-2018 standard.			
Packaging Materials	External:	PAPER/Corrugated	405 g			
		PAPER/Molded pulp	74 g			
	Internal:	PLASTIC/Polyethylene low density	3 g			
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer					
	to the HP General Specification for the Environment at					
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):					
	• Asbestos					
	Certain Azo Colorants					
		nated Flame Retardants – may not be used as flame retardants in plastics				
	• Cadmium					
		d Hydrocarbons				
	Chlorinated					
	• Formaldeh					
	_	ed Diphenyl Methanes				
		nates and sulfates ead compounds				
		xide Batteries				
		ishes must not be used on the external surface designed t	o he frequently handled or			
			o be frequently flandled of			
	carried by the user. • Ozone Depleting Substances					
	Polybrominated Biphenyls (PBBs)					
	Polybrominated Biphenyl Ethers (PBBEs)					
		nated Biphenyl Oxides (PBBOs)				
		nated Biphenyl (PCB)				
		nated Terphenyls (PCT)				
		hloride (PVC) – except for wires and cables, and certain re	tail packaging has been			
		emoved from most applications.	, 5 5			
		e Substances				
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)					



### **Packaging Usage**

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

## End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

**Global Citizenship Report** 

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

**Eco-label** certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC\_GBU\_Product\_Design\_ISO\_14K \_Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf





## **HP EliteDesk 800 Small Form Factor G8 series**

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:  • IT ECO declaration  • US ENERGY STAR®  • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <a href="http://www.epeat.net">http://www.epeat.net</a> for more information.						
System Configuration		The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop.					
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz 100VAC, 50Hz						
Normal Operation (Short idle)	11.855 watt	11.867 watt	11.8	61 watt			
Normal Operation (Long idle)	10.741 watt	10.789 watt	10.7	82 watt			
Sleep	0.862 watt	0.866 watt	0.85	7 watt			
Off	0.759 watt	0.762 watt	0.75	55 watt			
Heat Dissipation*	family. HP computers marked with the Environmental Protection Agency (EPA not offer ENERGY STAR® compliant con configured PC featuring a hard disk driv system.  115VAC, 60Hz	) ENERGY STAR® specificati figurations, then energy ef	ions for computers. If a mod fficiency data listed is for a t supply, and a Microsoft Wind	el family does ypically			
Normal Operation (Short		-					
idle)	40.42555 BTU/hr	40.46647 BTU/I	nr 40.446	01 BTU/hr			
Normal Operation (Long idle)	36.6268 BTU/hr	36.79049 BTU/l		62 BTU/hr			
Sleep	2.9394 BTU/hr	2.95306 BTU/h		37 BTU/hr			
Off	2.5881 BTU/hr	2.59842 BTU/h	r 2.5745	55 BTU/hr			
	<b>NOTE:</b> Heat dissipation is calculated ba one hour.	sed on the measured watts	s, assuming the service leve	l is attained for			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L <sub>WAd</sub> , bels)		Sound Pressure (L <sub>PAm</sub> , decibels)				
Typically Configured – Idle	3.1		20				
Fixed Disk–Random writes	3.5		23				
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:  Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.						
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC  Batteries used in the product do not contain:						
Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight							
	Battery size: CR2032 (coin cell)						





	Battery type	: Lithium			
Additional Information	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <a href="http://www.epeat.net">http://www.epeat.net</a> for more information.</li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.</li> <li>This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic*</li> <li>This product is 95.1% recycle-able when properly disposed of at end of life.</li> </ul> *NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.				
Deckasing Materials	External:	- · · · · · · · · · · · · · · · · · · ·			
Packaging Materials	Internal:	PAPER/Corrugated PLASTIC/EPE (Expanded Polyethylene)	1158 g 320 g		
	miternat.	PLASTIC/Polyethylene low density	28 q		
Material Usage	to the HP Ger http://www.l	minated Flame Retardants – may not be used as flame retained Hydrocarbons If Paraffins yde ed Diphenyl Methanes nates and sulfates ead compounds kide Batteries ishes must not be used on the external surface designed to e user. leting Substances nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs) nated Biphenyl Oxides (PBBOs) nated Biphenyl (PCB) lated Terphenyls (PCT) hloride (PVC) – except for wires and cables, and certain retainemoved from most applications.	f): ardants in plastics o be frequently handled or		

### **Features**

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The FUNEFIC disease (2002/05/FC) as a since as a second at the contract in factors of the
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
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## **HP EliteDesk 800 Tower G8 series**

This product has received or is in the process of being certified to the following approvals a be labeled with one or more of these marks:  • IT ECO declaration  • US ENERGY STAR®  • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.					
System Configuration	The configuration used for the En Desktop model is based on a Typi	ergy Consumption and Declared Nois cally Configured Desktop.	se Emissions data for the		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
Normal Operation (Short idle)	10.982 watt	11.285 watt	10.881 watt		
Normal Operation (Long idle)	9.96 watt	10.203 watt	9.892 watt		
Sleep	0.886 watt	0.888 watt	0.884 watt		
Off			0.759 watt		



Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does



					ta listed is for a typically I a Microsoft Windows® operating	
Heat Dissipation*	11!	5VAC, 60Hz	230VAC,	50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	37.4	4862 BTU/hr	38.48185 E	BTU/hr	37.10421 BTU/hr	
Normal Operation (Long idle)	33.9	7042 BTU/hr	34.79223 BTU/hr		33.7317 BTU/hr	
Sleep		2126 BTU/hr	3.02808 BTU/hr		3.0144 BTU/hr	
Off	2.59	9842 BTU/hr	2.60524 B	TU/hr	2.5881 BTU/hr	
	<b>NOTE:</b> Heat d one hour.	issipation is calculated t	oased on the measured	watts, assuming	the service level is attained for	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L <sub>WAd</sub> , bels)			Sound Pressure (L <sub>pAm</sub> , decibels)	
Typically Configured – Idle		3.2			21	
Fixed Disk–Random writes		3.3			22	
Longevity and Upgrading	features and	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:  Spare parts are available throughout the warranty period and or for up to "5" years after the end of				
Batteries		(s) in this product con	anly with EII Directive	2006/66/EC		
Additional Information	Batteries used in the product do not contain:  Mercury greater the1ppm by weight  Cadmium greater than 20ppm by weight  Battery size: CR2032 (coin cell)  Battery type: Lithium  • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.  • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.  • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).  • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information					
<ul> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11</li> <li>This product contains a minimum of 35% post-consumer recycled plastic (by wt ITE-derived post-consumer recycled plastic*</li> <li>This product is 95.1% recycle-able when properly disposed of at end of life.</li> </ul> *NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.						
Packaging Materials	External:	PAPER/Corrugated	<u> </u>		1114 g	
		PAPER/Molded Pu	lp		788 g	
	Internal:		ene low density - LD		44 g	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at <a href="http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf">http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf</a> ):  • Asbestos  • Certain Azo Colorants					



## Features

	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	• Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	• Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin 0xide (TBT0)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
and necycling	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

## HP EliteOne 800 G8 23.8-in All-in-One

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<b>Eco-Label Certifications &amp;</b> This product has received or is in the process of being certified to the following approvals						
declarations	be labeled with one or more of these marks:					
	IT ECO declaration					



## Features

System Configuration	<ul> <li>US ENERGY STAR®</li> <li>US Federal Energy Manageme</li> <li>Based on US EPEAT® registrat varies by country. Visit http://</li> <li>TCO Certified Edge</li> <li>China Energy Conservation Pr</li> <li>China State Environmental Pr</li> <li>Taiwan Green Mark</li> <li>Korea Eco-label</li> <li>Japan PC Green label*</li> </ul> The configuration used for the Ener in-One PC model is based on a typic power supply, and a Microsoft Wind	tion according to IEEE 1 /www.epeat.net for mo rogram (CECP) rotection Administration rgy Consumption and De cally configured PC featu	re information n (SEPA) eclared Noise B uring a hard di	n Emissions data for the All-
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz		100VAC, 50Hz
Normal Operation (Short idle)	14.97 watt	15.06 watt		14.79 watt
Normal Operation (Long idle)	2.36 watt	2.45 watt		2.18 watt
Sleep	2.4 watt	2.42 watt		2.37 watt
Off	0.97 watt	0.98 watt		0.94 watt
	NOTE: Energy efficiency data listed is for family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv	ENERGY STAR® Logo are co ENERGY STAR® specificat figurations, then energy e	ions for comput fficiency data lis	ters. If a model family does sted is for a typically
Heat Dissipation*	family. HP computers marked with the E Environmental Protection Agency (EPA)	ENERGY STAR® Logo are co ENERGY STAR® specificat figurations, then energy e	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically
Normal Operation (Short idle)	family. HP computers marked with the E Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant conf configured PC featuring a hard disk driv system.	ENERGY STAR® Logo are co ENERGY STAR® specificat figurations, then energy e re, a high efficiency power	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically Iicrosoft Windows® operating
Normal Operation	family. HP computers marked with the E Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant conf configured PC featuring a hard disk driv system.	ENERGY STAR® Logo are controlled the ENERGY STAR® specificate figurations, then energy energy and the Energy energy energy and the Energy	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating
Normal Operation (Short idle) Normal Operation (Long idle) Sleep	family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv system.  115VAC, 60Hz 51.0477 BTU/hr 8.0476 BTU/hr 8.184 BTU/hr	ENERGY STAR® Logo are content of the ENERGY STAR® specificated figurations, then energy energy and the Energy energy and the Energy energy and the Energy energy and the Energy e	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr  8.0817 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle)	family. HP computers marked with the E Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant conf configured PC featuring a hard disk driv system.  115VAC, 60Hz  51.0477 BTU/hr  8.0476 BTU/hr	ENERGY STAR® Logo are content of ENERGY STAR® specificated of ENERGY STAR® specificated figurations, then energy even, a high efficiency power and the energy even of Energy Energy STATE of E	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv system.  115VAC, 60Hz 51.0477 BTU/hr 8.0476 BTU/hr 8.184 BTU/hr	ENERGY STAR® Logo are content of ENERGY STAR® specificated in the specificate figurations, then energy even a high efficiency power in the specific of the spe	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr  8.0817 BTU/hr  3.2054 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions (in accordance with	family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv system.  115VAC, 60Hz 51.0477 BTU/hr 8.0476 BTU/hr 8.184 BTU/hr 3.3077 BTU/hr	ENERGY STAR® Logo are content of ENERGY STAR® specificated in the specificate figurations, then energy even a high efficiency power in the specific of the spe	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr  8.0817 BTU/hr  3.2054 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv system.  115VAC, 60Hz 51.0477 BTU/hr 8.0476 BTU/hr 8.184 BTU/hr 3.3077 BTU/hr NOTE: Heat dissipation is calculated bas one hour.  Sound Power (L <sub>WAd</sub> , bels)	ENERGY STAR® Logo are content of ENERGY STAR® specificated in the specificate figurations, then energy even a high efficiency power in the specific of the spe	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr  8.0817 BTU/hr  3.2054 BTU/hr e service level is attained for and Pressure Am, decibels)
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	family. HP computers marked with the Environmental Protection Agency (EPA) not offer ENERGY STAR® compliant configured PC featuring a hard disk driv system.  115VAC, 60Hz 51.0477 BTU/hr 8.0476 BTU/hr 8.184 BTU/hr 3.3077 BTU/hr NOTE: Heat dissipation is calculated basone hour.	ENERGY STAR® Logo are content of ENERGY STAR® specificated in the specificate figurations, then energy even a high efficiency power in the specific of the spe	ions for comput fficiency data lis supply, and a M	ters. If a model family does sted is for a typically dicrosoft Windows® operating  100VAC, 50Hz  50.4339 BTU/hr  7.4338 BTU/hr  8.0817 BTU/hr  3.2054 BTU/hr e service level is attained for





	Spare parts are available throughout the warranty period and or for up to "5" years after the end o production.					
Batteries		s) in this product comply with EU Directive 2006/66/EC				
	Batteries used in the product do not contain:  Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight  Battery size: CR2032 (coin cell) Battery type: Lithium					
Additional Information	This pr	oduct is in compliance with the Restrictions of Hazardou	s Substances (RoHS) directive			
	• This HI (WEEE)	/65/EC. P product is designed to comply with the Waste Electrical Directive – 2002/96/EC.				
		oduct is in compliance with California Proposition 65 (Stand Toxic Enforcement Act of 1986).	ate of California; Safe Drinking			
ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Based on US registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by cou www.epeat.net for more information.						
	Plastic IS0104	s parts weighing over 25 grams used in the product are r 13.	narked per ISO11469 and			
	• This pr 1680.1	oduct contains 51.7% post-consumer recycled plastic (b 1-2018 standard, criterion 4.2.1.1. oduct is 97.8% recycle-able when properly disposed of a	-			
Packaging Materials	External:	PAPER/Corrugated	1.488 g			
	Internal:	PLASTIC/Polyethylene Expanded - EPE	1.052 g			
		ackaging material contains at least xx% recycled content				
RoHS Compliance	HP Inc. comp restrictions in products wo	ed paper packaging materials contains at least xx% recy lies fully with materials regulations. We were among the n the European Union (EU) Restriction of Hazardous Subs Idwide through the HP GSE. HP has contributed to the de Europe, as well as China, India, and Vietnam.	first companies to extend the tances (RoHS) Directive to our			
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.					
	requirements	roluntary objective to achieve worldwide compliance witl s for virtually all relevant products by July 2013, and we commitment to include further restricted substances as	will continue to extend the			
	To obtain a c	opy of the HP RoHS Compliance Statement, see HP RoHS	position statement.			
Material Usage	to the HP Ger http://www.l • Asbestos • Certain Azo • Certain Bro • Cadmium	minated Flame Retardants – may not be used as flame ro Hydrocarbons	odf):			



### Features

	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	• Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	<ul> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
	Plastic packaging materials are marked according to 150 11469 and Div 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

### HP EliteOne 800 G8 27 All-in-One PC

Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may
declarations	be labeled with one or more of these marks:
	IT ECO declaration
	US ENERGY STAR®
	US Federal Energy Management Program (FEMP)



## Features

System Configuration	See http://www.epeat HP's 3rd party option s http://www.hp.com/g  TCO Certified Edge China Energy Conserva China State Environme Taiwan Green Mark Korea Eco-label Japan PC Green label*	net for registrati store for solar ger o/options. ation Program (CE ental Protection A Energy Consumpt cypically configure	on status by cour nerator accessorion CP) dministration (SE ion and Declared ed PC featuring a	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC		100VAC, 60Hz
Normal Operation (Short idle)	16.05 watt	16.14	watt	15.88 watt
Normal Operation (Long idle)	2.23 watt	2.32 v	vatt	2.05 watt
Sleep	2.26 watt	2.28 v	vatt	2.23 watt
Off	0.93 watt	0.94 v		0.9 watt
	not offer ENERGY STAR® compliant	t configurations, the	en energy efficiency	computers. If a model family does data listed is for a typically and a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	<b>115VAC, 60Hz</b> 54.7305 BTU/hr	<b>230VAC</b> 55.0374		<b>100VAC, 60Hz</b> 54.1508 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle)	54.7305 BTU/hr 7.6043 BTU/hr	55.0374 7.9112 E	BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle) Sleep	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr	55.0374 7.9112 E 7.7748 E	BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr 3.1713 BTU/hr NOTE: Heat dissipation is calculate one hour.	55.0374 7.9112 E 7.7748 E 3.2054 E	BTU/hr BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr 3.069 BTU/hr ning the service level is attained for
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr 3.1713 BTU/hr NOTE: Heat dissipation is calculate one hour. Sound Power	55.0374 7.9112 E 7.7748 E 3.2054 E	BTU/hr BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr 3.069 BTU/hr ning the service level is attained for Sound Pressure
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr 3.1713 BTU/hr NOTE: Heat dissipation is calculate one hour.  Sound Power (L <sub>WAd</sub> , bels)	55.0374 7.9112 E 7.7748 E 3.2054 E	BTU/hr BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr 3.069 BTU/hr ning the service level is attained for Sound Pressure (L <sub>pAm</sub> , decibels)
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr 3.1713 BTU/hr NOTE: Heat dissipation is calculate one hour.  Sound Power (L <sub>WAd</sub> , bels)	55.0374 7.9112 E 7.7748 E 3.2054 E	BTU/hr BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr 3.069 BTU/hr ning the service level is attained for  Sound Pressure (L <sub>pAm</sub> , decibels)
Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off  Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	54.7305 BTU/hr 7.6043 BTU/hr 7.7066 BTU/hr 3.1713 BTU/hr NOTE: Heat dissipation is calculate one hour.  Sound Power (L <sub>WAd</sub> , bels)	55.0374 7.9112 E 7.7748 E 3.2054 E	BTU/hr BTU/hr BTU/hr BTU/hr	54.1508 BTU/hr 6.9905 BTU/hr 7.6043 BTU/hr 3.069 BTU/hr ning the service level is attained for Sound Pressure (L <sub>pAm</sub> , decibels)



## Features

	• 1 5.25" ex	ternal supporting optical drive		
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC			
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight  Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	• This	product is in compliance with the Restrictions of Ha	azardous Substances (RoHS)	
	• This (WE	ctive - 2011/65/EC.  HP product is designed to comply with the Waste E EE) Directive – 2002/96/EC.		
		product is in compliance with California Proposition king Water and Toxic Enforcement Act of 1986).	1 65 (State of California, Safe	
	regi	RGY STAR® certified. EPEAT® 2019 registered where stration according to IEEE 1680.1-2018 EPEAT®. EP ://www.epeat.net for more information.		
	• Plas	tics parts weighing over 25 grams used in the produ	uct are marked per ISO11469 and	
		1043. product contains 72.2% post-consumer recycled p	lastic (by wt.) according to IEEE	
		0.1-2018 standard, criterion 4.2.1.1. product is 98% recycle-able when properly dispose	nd of at and of life	
	11113	product is 50% recycle-able when property dispose	ed of at end of the.	
Packaging Materials	External:	PAPER/Corrugated	1.510 g	
	Internal:	PLASTIC/Polyethylene Expanded - EPE packaging material contains at least xx% recycled co	1.520 g	
		ted paper packaging materials contains at least xx%		
RoHS Compliance	HP Inc. comp restrictions in products woo legislation in	lies fully with materials regulations. We were amon n the European Union (EU) Restriction of Hazardous Idwide through the HP GSE. HP has contributed to t Europe, as well as China, India, and Vietnam.	g the first companies to extend the Substances (RoHS) Directive to our he development of related	
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.			
	To obtain a c	opy of the HP RoHS Compliance Statement, see: HP	RoHS position statement.	
Material Usage	to the HP Gei	does not contain any of the following substances in neral Specification for the Environment at np.com/hpinfo/globalcitizenship/environment/supp		
		estos		
		ain Azo Colorants ain Brominated Flame Retardants – may not be use	d as flame retardants in plastics	
	- cert	an Brommatea Ftame Netardants - may not be use	a as manie retardants in plastics	



## Features

	Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Bis(2-Ethylhexyl) phthalate (DEHP)
	Benzyl butyl phthalate (BBP)
	Dibutyl phthalate (DBP)
	Diisobutyl phthalate (DIBP)
	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently
	handled or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has
	been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	<ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> </ul>
	<ul> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> </ul>
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	<ul> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> </ul>
	Reduce size and weight of packages to improve transportation fuel efficiency.
	<ul> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
	1 tustic packaging materials are marked according to 150 11405 and bit 0120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

Features		
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf	





**Features** 

#### SERVICE AND SUPPORT

#### HP EliteDesk 800 G8 Tower PC

On-site Warranty<sup>1</sup>: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day<sup>2</sup> service for parts and labor and includes free support 24 x 7<sup>3</sup>. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.<sup>4</sup>

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

#### **HP EliteDesk 800 G8 Small Form Factor PC**

On-site Warranty<sup>1</sup>: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day<sup>2</sup> service for parts and labor and includes free support 24 x 7<sup>3</sup>. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.<sup>4</sup>

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

### HP EliteDesk 800 G8 Desktop Mini PC

On-site Warranty<sup>1</sup>: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day<sup>2</sup> service for parts and labor and includes free support 24 x 7<sup>3</sup>. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/qo/cpc.<sup>4</sup>

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



#### **Features**

#### HP EliteOne 800 G8 24 & 27 All-in-One PC

On-site Warranty<sup>1</sup>: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day<sup>2</sup> service for parts and labor and includes free support 24 x 7<sup>3</sup>. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.<sup>4</sup>

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

#### **CERTIFICATION AND COMPLIANCE**

#### **Energy Efficiency Compliance**

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

## **PROCESSORS**

### Intel® 11th Generation Core™ Processors

All HP EliteDesk 800 G8 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G8 Business PC.

Intel® Management Engine (ME) v15 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 15 includes the following advanced management functions:

- Support for configuration of Intel ME 15.0 capabilities
- No reset after provisioning
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
  - Public Key Infrastructure
- Profile Editor and Profile Editor Plugin Interface
- Required Permissions for Solutions Framework





Technical Specifications – Display Panel Specifications

#### **DISPLAY PANEL SPECIFICATIONS**

## 23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points

Non-Touch Support HW low blue light feature

TypeIPS WLED Backlit LCDActive area (mm)527.04 x 296.46Native Resolution (HxV)1920 x 1080

**Refresh Rate** 60 Hz @ 1920 x 1080

Aspect ratio 16:9

**Pixel pitch (HxV)(mm)** 0.2745 x 0.2745

Contrast ratio 1000:1
Brightness\* 250nits
Viewing angle (HxV) 178 ° x 178 °

Backlight lamp life (to half brightness) 30,000 hours minimum

**Color support** Up to 16.7 million colors with the use of FRC technology

Color gamut NTSC 72%
Anti-glare Yes\*
Response Time 14ms

**Default color temperature** Warm (6500K)

NOTE\*: Actual brightness will be lower with touchscreen or HP Sure View

## 27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (2560 x 1440) non Touch Support HW low blue light feature

 Type
 IPS WLED Backlit LCD

 Active area (mm)
 596.736 x 335.664

 Native Resolution (HxV)
 2560 x 1440

**Refresh Rate** 60 Hz @ 2560 x 1440

Aspect ratio 16:9

**Pixel pitch (HxV)(mm)** 0.2331 x 0.2331

Contrast ratio1000:1Brightness\*250nitsViewing angle (HxV)178° x 178°

**Backlight lamp life (to half brightness)** 30,000 hours minimum **Color support** Up to 16.7 million colors

Color gamutNTSC 72%Anti-glareYes\*Response Time14ms

**Default color temperature** Warm (6500K)

2. For All in One only Intel® HD Graphics (integrated)

NOTE\*: Actual brightness will be lower with touchscreen or HP Sure View



<sup>1.</sup> All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot
Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel



## Technical Specifications – Graphics

#### **GRAPHICS**

### HP EliteDesk 800 G8 Desktop Mini PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

**HDMI (optional)** Supports HDMI 2.0b features

Supports HDCP 2.3

Supports audio over HDMI

VGA (optional) VGA output

**USB-C® DP Alt Mode (optional)** DisplayPort over the optional USB-C® module

**Memory** The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to Graphics/Video API Support HEV

up to 16 bits/color HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

## Nvidia® GeFORCE® GTX1660 Ti

Architecture Discrete GPU

Nvidia® GPU drives the integrated panel and all of the graphics output ports

**DisplayPort** Maximun pixel clock :1.3 GHz pixels per second

Maximun bandwidth: 25.92 Gbps per connector (FEC Disable)

**HDMI** Supports HDMI 2.0b features

Supports HDCP 2.2, HDR

Memory 6GByte, 192bit wide GDDR6

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

OpenGL 4.6

**Display Port** Support DP1.4(DSC1.2a)

Maximum pixel clock: 1.3 GHz pixels per second

Maximum bandwidth: 25.92 Gbps per connector (FEC Disable)

**Max. Resolution (HDMI)** 4096 x 2160@60Hz

Max. Resolution (DP) 5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings

**Port Availability** (3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port



## Technical Specifications – Graphics

#### **HP EliteDesk 800 G8 Tower PC**

Intel® UHD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ 1.4 Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

**HDMI (optional)** Supports HDMI 2.0b features

Supports HDCP 2.3

Supports BT2020 and HDR playback (7th Gen processors only)

VGA (optional) VGA ouput

**USB-C® DP Alt Mode (optional)** DisplayPort over the optional USB-C® module

**Memory** The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

#### NVIDIA® GeForce® RTX 3070 Graphics Card

 Engine Clock
 1730 MHz

 Memory Clock
 8000 MHz

 Memory Size(width)
 8 GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution (HDMI)
 4096x2160@60Hz

 Max. Resolution (DP)
 7680x4320@60Hz

Multi Display Support4 displaysHDCP ComplianceYes

Rear I/O connectors (bracket) HDMIx1+ DPx3

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) <220W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

### AMD® Radeon™ RX 550X Graphics Card

Engine Clock 1183MHz
Memory Clock 6 Gbps
Memory Gire (width) 4 GB (120)

**Memory Size (width)** 4 GB (128-bit)

Memory Type GDDR5

 Max. Resolution (HDMI)
 4096x2160 @ 60Hz

 Max. Resolution (DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYes

Rear I/O connectors (bracket) HDMI, DPx2

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)



## Technical Specifications – Graphics

Total power consumption (W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

### **NVIDIA® Quadro P620 Graphics Card**

Engine Clock1354 MHzMemory Clock2500 MHzMemory Size (width)2GB (128-bit)Memory Type128M x 32 GDDR5Max. Resolution (DP)5120x2880@60Hz

Multi Display Support 4 displays
HDCP Compliance Yes
Rear I/O connectors (bracket) mDPx4

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) <40W

PCB form-factor with bracket LP PCB with LP bracket

### **NVIDIA® Quadro P400 Graphics Card**

Engine Clock1252 MHzMemory Clock2000 MHzMemory Size (width)2GB (64-bit)Memory Type256M x 32 GDDR5Max. Resolution (DP)5120x2880@60Hz

Multi Display Support3 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

**Total power consumption (W)** <30W

PCB form-factor with bracket LP PCB with LP bracket

#### AMD® Radeon™ R7 430 Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size (width)2 GB (64-bit)Memory Type256M x 32 GDDR5Max. Resolution (HDMI)2048x1536

Max. Resolution (DP) 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors (bracket)VGA+DP

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



## Technical Specifications – Graphics

## AMD® Radeon™ R7 430 Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size (width)2 GB (64-bit)Memory Type256M x 32 GDDR5

 Max. Resolution (DP)
 256M x 32 GDDR5

 4096x2160@60Hz

Multi Display Support2 displaysHDCP Complianceyes

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

DPx2

**Total power consumption (W)** <50W

Rear I/O connectors (bracket)

PCB form-factor with bracket LP PCB with FH/LP bracket



## Technical Specifications – Graphics

#### **HP EliteDesk 800 G8 Small Form Factor PC**

Intel® HD Graphics (integrated)

VGA Controller Integrated

**DisplayPort™ 1.4** Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and

Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by

Intel® Graphics

**HDMI (optional)** Supports HDMI 2.0b features

Supports HDCP 2.3

Supports audio over HDMI

VGA (optional) VGA Output

**USB-C® DP Alt Mode (optional)** DisplayPort over the optional USB-C® module

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

### AMD® Radeon™ R7 430 Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size (width)1 GB (64-bit)Memory Type256M x 32 GDDR5Max. Resolution (HDMI)2048x1536

Max. Resolution (DP) 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors (bracket)VGA+DP

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

**Total power consumption (W)** <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

### AMD® Radeon™ R7 430 Graphics Card

 Engine Clock
 780 MHz

 Memory Clock
 1100 MHz

 Memory Size (width)
 1 GB (64-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution (DP)
 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceyesRear I/O connectors (bracket)DPx2

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

**Total power consumption (W)** <50W



## Technical Specifications – Graphics

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ RX550 Graphics Card

**Engine Clock** 1183MHz **Memory Clock** 6 Gbps

Memory Size (width) 4 GB (128-bit)

Memory Type GDDR5

 Max. Resolution (HDMI)
 4096x2160 @ 60Hz

 Max. Resolution (DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors (bracket)HDMI, DP

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

**Total power consumption (W)** <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

AMD Radeon™ 520 Graphics Card

 Engine Clock
 780 MHz

 Memory Clock
 1100 MHz

 Memory Size (width)
 1 GB (32-bit)

 Memory Type
 256M x 32 GDDR5

 Max. Resolution (DP)
 2048x1536@60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors (bracket)VGA+DP

**Cooling (active/passive)** Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



## Technical Specifications – Graphics

### HP EliteOne 800 G8 23.8-in All-in-One

Intel® UHD Graphics (integrated)

**VGA Controller** Integrated

DisplayPort™ 1.4 Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

Stream Technology for a maximum of 3 displays (including the integrated panel and all

attached displays)

**HDMI-in** Support HDMI-In

**Memory** The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth Graphics/Video API Support up to 10 bits/color HEVC 10b Enc/Dec HW

VP9 10b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz



## Technical Specifications – Storage

#### **STORAGE**

#### 500GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size32 MBLogical Blocks976,773,168Seek Time11 ms (Average)Height1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 1TB 7200RPM 3.5in SATA HDD

Capacity 1 TB
Rotational Speed 7,200 rpm
Interface SATA 6 Gb/s
Buffer Size 64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

**Operating Temperature** 41° to 131° F (5° to 55° C)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 2TB 7200RPM 3.5in SATA HDD

Capacity 2 TB

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size 128 MB

 Logical Blocks
 3,907,050,336

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm

Width (nominal) Media diameter: 3.5 in/88.9 mm

Physical size: 4 in/102 mm

**Operating Temperature** 41° to 131° F (5° to 55° C)



## Technical Specifications – Storage

#### 500GB 7200RPM 2.5in SATA HDD

Capacity 500 GB **Rotational Speed** 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128 MB **Logical Blocks** 976,773,168 **Seek Time** 12 ms (Average) 0.283 in/7.2 mm (Max.) Height Width (nominal) 2.75 in/70 mm (nominal)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

41° to 131° F (5° to 55° C)

#### 1TB 7200RPM 2.5in SATA HDD

**Operating Temperature** 

Capacity 1 TB **Rotational Speed** 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128 MB **Logical Blocks** 1,953,525,168 **Seek Time** 12 ms (Average) Height 0.283 in/7.2 mm (Max.) 2.75 in/70 mm (nominal) Width (nominal) **Operating Temperature** 41° to 131° F (5° to 55° C)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 2TB 5400RPM 2.5in SATA HDD

Capacity 2 TB

Rotational Speed 5,400 rpm
Interface SATA 6 Gb/s

Buffer Size 128 MB

Logical Blocks 3,907,050,336

Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



## Technical Specifications – Storage

## 500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

 Interface
 SATA 6 Gb/s

 Buffer Size
 128 MB

 Logical Blocks
 976,773,168

 Seek Time
 12 ms (Average)

 Height
 0.283 in/7.2 mm (Max.)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity 500 GB

**Architecture** Self-Encrypting (SED) Solid State Drive with SATA interface

Interface SATA 6 Gb/s

Buffer Size 128 MB

Logical Blocks 976,773,168

Seek Time 12 ms (Average)

Height 0.283 in/7.2 mm (Max.)

Width 2.75 in/70 mm (nominal)

Operating Temperature 41° to 131° F (5° to 55° C)

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 256GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 256 GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3
Maximum Sequential Read Up to 1600

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



## Technical Specifications – Storage

#### **512GB M.2 2280 PCIe NVMe SSD**

Drive Weight < 10g
Capacity 512 GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 1TB M.2 2280 PCIe NVMe SSD

**Drive Weight** < 10g 1 TB Capacity Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 2200MB/s **Maximum Sequential Write** Up to 1800MB/s **Logical Blocks** 1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features APST: ASPM L1.2: NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10a 256GB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2



## Technical Specifications – Storage

### 512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g
Capacity 512 GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 2900MB/sMaximum Sequential WriteUp to 1100MB/sLogical Blocks1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### 1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10q 1 TB Capacity Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 3480MB/s **Maximum Sequential Write** Up to 3037MB/s

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

2,000,409,264

Features TRIM: ASPM L1.2

**Logical Blocks** 

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10a 2 TB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 3500MB/s **Maximum Sequential Write** Up to 3000MB/s **Logical Blocks** 3,907,029,168

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2



Technical Specifications – Storage

### 256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10g
Capacity 256 GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 2700MB/sMaximum Sequential WriteUp to 1000MB/sLogical Blocks500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### 512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

**Drive Weight** < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen3 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

## 256GB Intel® PCIe® NVMe™ QLC + 16 GB Intel® Optane™

**Drive Weight** < 10a Capacity 256 GB Height 2.38mm Length 80mm Width 22mm Interface PCIe Gen3 **Maximum Sequential Read** Up to 1450MB/s **Maximum Sequential Write** Up to 500MB/s **Logical Blocks** 500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2



## Technical Specifications – Storage

### 512GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

**Drive Weight** < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIe Gen3 **Maximum Sequential Read** Up to 2400MB/s **Maximum Sequential Write** Up to 1300MB/s **Logical Blocks** 1.000.215.215

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### 256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10g Capacity 256GB Height 2.38mm Length 80mm Width 22<sub>mm</sub> Interface PCIE Gen4 **Maximum Sequential Read** Up to 6400MB/s **Minimum Sequential Write** Up to 2700MB/s **Logical Blocks** 500,118,192

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

## 512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10g Capacity 512 GB Height 2.38mm Length 80mm Width 22<sub>mm</sub> Interface PCIE Gen4 **Maximum Sequential Read** Up to 6600MB/s **Maximum Sequential Write** Up to 5100MB/s **Logical Blocks** 1.000.215.216

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

**Features** APST; ASPM L1.2; NVME spec 1.2





Technical Specifications – Storage

#### 1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10a 1 TB Capacity Height 2.38mm Length 80mm Width 22mm **Interface** PCIE Gen4 **Maximum Sequential Read** Up to 7100MB/s **Maximum Sequential Write** Up to 5200MB/s **Logical Blocks** 2,000,409,264

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

### 2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

**Drive Weight** < 10q Capacity 2 TB 2.38mm Height Length 80mm Width 22mm Interface PCIE Gen4 **Maximum Sequential Read** Up to 7100MB/s **Maximum Sequential Write** Up to 5200MB/s **Logical Blocks** 4,000,797,360

**Operating Temperature** 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

**NOTE:** For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

#### **OPTICAL DISC DRIVES**

### **HP 9.5mm Slim DVD-ROM Drive**

**Height** 9.5 mm height

**Orientation** Either horizontal or vertical

Interface type SATA/ATAPI

**Dimensions (W x H x D)** 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140q) without bezel

Read Speeds DVD+R/-R/+RW/

-RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

Access time Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)



## Technical Specifications – Storage

(typical reads, including

settling)

Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

**Power** Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions

(operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

#### **HP 9.5mm Slim DVD Writer Drive**

**Height** 9.5 mm height

**Orientation** Either horizontal or vertical

Interface type SATA/ATAPI

**Disc recording capacity** Up to 8.5 GB DL or 4.7 GB standard

**Dimensions (W x H x D)** 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)
Write Speeds DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X

Read Speeds DVD-R DL, DVD+R DL - Up to 8X

DVD+R, DVD-R - Up to 8X

 $\ensuremath{\mathsf{DVD}\text{-}\mathsf{ROM}}$  DL,  $\ensuremath{\mathsf{DVD}\text{-}\mathsf{ROM}}$  - Up to 8X

CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X

Access time

(typical reads, including

settling)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

**Power** Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

**Environmental conditions** 

(operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications – Networking and Communications

## **NETWORKING AND COMMUNICATIONS**

Intel® I219-LM 1 Gigabit	Network Connection LOM (vPro)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption  Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components

Intel® I225-LM 2.5 Giga	bit Network Connection LOM (non-vPro)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)
	4. 2.5 Gbit/s operation( 2.5GBASE-T; IEEE 802.3bz Clause 126)
	5. Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
	IEEE 802.3i 10BASE-T
	IEEE 802.3u 100BASE-TX
	IEEE 802.3ab 1000BAE-T
	IEEE 802.3bz 2.5GBASE-T



## Technical Specifications – Networking and Communications

Performance	TCP/IP/UDP Checksum Offload (configurable)				
	Protocol Offload (ARP & NS)				
	Large send offload and Giant send offload				
	Receiving Side Scaling (hash mode only)				
	Jumbo Frame 9K				
Power consumption	Cable Disconnetion: 25mW				
	100Mbps Full Run: 450mW				
	1000bp Full Run: 1000mW				
	WoL Enable(S3/S4/S5): 50mW				
	WoL Disable(S3/S4/S5): 25mW				
Power	ACPI compliant – multiple power modes				
Management	Situation-sensitive features reduce power consumption				
	Advanced link down power saving for reducing link down power consumption				
Management Interface	Auto MDI/MDIX Crossover cable detection				
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);				
	Wake-on-LAN from off (Magic Packet only)				
	PXE 2.1 Remote Boot				
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))				
	Comprehensive diagnostic and configuration software suite				
	Virtual Cable Doctor for Ethernet cable status				
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components				



Technical Specifications – Networking and Communications

RJ-45
PCI (Intel proprietary) + SMBus
10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
Auto-Negotiation (Automatic Speed Selection)
Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE 802.1p QoS (Quality of Service) Support
IEEE 802.1q VLAN support
IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
IEEE 802.3az EEE (Energy Efficient Ethernet)
TCP/IP/UDP Checksum Offload (configurable)
Protocol Offload (ARP & NS)
Large send offload and Giant send offload
Receiving Side Scaling
Jumbo Frame 9K
Cable Disconnetion: 25mW
100Mbps Full Run: 450mW
1000bp Full Run: 1000mW
WoL Enable(S3/S4/S5): 50mW
WoL Disable(S3/S4/S5): 25mW
ACPI compliant – multiple power modes
Situation-sensitive features reduce power consumption
Advanced link down power saving for reducing link down power consumption
Auto MDI/MDIX Crossover cable detection
Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
PXE 2.1 Remote Boot
Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
Comprehensive diagnostic and configuration software suite
Virtual Cable Doctor for Ethernet cable status





Technical Specifications – Networking and Communications

## Intel Wi-Fi 6 AX201 + BT5.1 (802.11ax 2x2, vPro, supporting gigabit data rate\*) vPro

**NOTE\*** Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi CERTIFIED™
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security <sup>3</sup>	<ul> <li>IEEE and Wi-Fi CERTIFIED™ 64/128bit WEP encryption for a/b/g mode only</li> </ul>
•	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power <sup>2</sup>	• 802.11b: +17dBm minimum
•	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum
	• 802.11n HT20(5GHz): +14dBm minimum
	• 802.11n HT40(5GHz) : +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz) : +12dBm minimum
	COLLITION THE TOTAL THE



Technical Specifications – Networking and Communications

		GHz): +10dBm minimum	
	• 802.11ax HE160(5GHz) : +10dBm minimum		
Power Consumption	• Transmit mode: 2.0 W		
	• Receive mode: 1.		
	· · ·	80 mW (WLAN Associated)	
		V (WLAN unassociated)	
	<ul> <li>Connected Stand</li> </ul>	by: 10mW	
	<ul> <li>Radio disabled: 8</li> </ul>		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity <sup>3</sup>		-93.5dBm maximum	
		: -84dBm maximum	
	• 802.11a/g, 6Mbp	s: -86dBm maximum	
	• 802.11a/g, 54Mb	ps: -72dBm maximum	
	• 802.11n, MCS07:	-67dBm maximum	
	• 802.11n, MCS15:	-64dBm maximum	
	• 802.11ac, MCS0(\	VHT80): -84dBm maximum	
	• 802.11ac, MCS9(\	VHT80): -59dBm maximum	
	• 802.11ac, MCS9(\	VHT160): -58.5dBm maximum	
	•802.11ax, MCS11	(HE40): -57dBm maximum	
		(HE80): -54dBm maximum	
		(HE160): -53.5dBm maximum	
Antenna type		enna with spatial diversity, mounted in the display enclosure	
		al band 2.4/5 GHz antennas are provided to the card to support WLAN	
		ions and Bluetooth communications	
Form Factor		iniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x		
	2. Type 1216: 1.67		
Weight	1. Type 2230: 2.8g		
weight	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
remperature	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
numuity	Non-operating	5% to 95% (non-condensing)	
Alatanda		0 to 10,000 ft (3,048 m)	
Altitude	Operating		
LED A salestan	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
HP Integrated Module with Blu	etooth <sup>®</sup> 4.0/4.1/4.2	/5.0/5.1 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1	Compliant	
Frequency Band	2402 to 2480 MHz		
Number of Available Channels		7/CU\	
Number of Available Chaimets	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	, , , , , ,		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels.		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
T			
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum		
	transmit power of +	9.5 dBm for BR and EDR.	





Technical Specifications – Networking and Communications

Power Consumption	Peak (Tx) 330 mW		
	Peak (Rx) 230 mW		
	Selective Suspend 17 mW		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950		
	UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance		
	LE Link Layer Ping		
	LE Dual Mode		
	LE Link Layer		
	LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance		
	LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Extended Scanner Filter Policies		
	LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2		
	Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		
	BT5.1		
	ESR9/10 Compliance		
	LE Advertisement Extensions		
	Channel Selection Algo		
	Limited High Duty Cycle Non-Connectable Advertising		
	2Mbps LE		
	LE Long Range		
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components		

## Intel Wi-Fi 6 AX201 + BT5.1 (802.11ax 2x2, non-vPro, supporting gigabit data rate\*) non-vPro

**NOTE\*** Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r



Technical Specifications – Networking and Communications

	IEEE 802.11v
Interoperability	Wi-Fi CERTIFIED™
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security <sup>3</sup>	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only
_	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power <sup>2</sup>	• 802.11b: +17dBm minimum
	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum
	• 802.11n HT20(5GHz): +14dBm minimum
	• 802.11n HT40(5GHz): +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	Transmit mode 2.0 W
<del>-</del>	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby:10mW
	• Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
-	802.11 compliant power saving mode
Receiver Sensitivity <sup>3</sup>	•802.11b, 1Mbps: -93.5dBm maximum
•	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 002.11d/y, 54Mbp5/ 2ubiii iiidxiiiiuiii
	• 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum
	802.11a, MCS07: -67dBm maximum     802.11n, MCS15: -64dBm maximum





Technical Specifications – Networking and Communications

		(VHT80): -59dBm maximum		
		(VHT160): -58.5dBm maximum		
		(HE40): -57dBm maximum		
	•802.11ax, MCS11(HE80): -54dBm maximum			
		(HE160): -53.5dBm maximum		
Antenna type		tenna with spatial diversity, mounted in the display enclosure		
		al band 2.4/5 GHz antennas are provided to the card to support WLAN		
		tions and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface			
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm			
	2. Type 1216: 1.67 x 12.0 x 16.0 mm			
Weight	1. Type 2230: 2.8g	]		
	2. Type 126: 1.3g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	-40° to 176° F (-40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
_	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity		o OFF; LED Off – Radio ON		
HP Integrated Module with Blueto	ooth® 4.0/4.1/4.2/	5.0/5.1 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1			
-	2402 to 2480 MHz	Computant		
Frequency Band				
Number of Available Channels	Legacy : 0~79 (1 MI BLE : 0~39 (2 MHz/			
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps			
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels.			
	Legacy: Asynchronous Connection Unented tinks up to 3, 64 kbps, voice channels.  Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5)			
	or 864 kbps symme			
Transmit Power	-	mponent shall operate as a Class II Bluetooth® device with a maximum		
Transmit Fower	transmit power of +9.5 dBm for BR and EDR.			
Power Consumption		· 5.5 doint for bit did Lbit.		
rowei consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW Selective Suspend 17 mW			
Disease ask® Coff.				
Bluetooth® Software Supported	MICROSOFT WINDOWS	Bluetooth® Software		
Link Topology	<u> </u>			
Power Management	Microsoft Windows	ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 1	5C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826			
	Low Voltage Directive IEC950			
	UL, CSA, and CE Ma			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Co			
Stactooth Florites Supported	LE Link Layer Ping	omphanee		
	LE Dual Mode			
	LE Link Layer			
		Directed Advertising		
		on Oriented Channels		
	Train Nudging & Int			
		tertuceu Jeur		





## Technical Specifications – Networking and Communications

DT4 2 FCD00 Compliance
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)
BT5.1
ESR9/10 Compliance
LE Advertisement Extensions
Channel Selection Algo
Limited High Duty Cycle Non-Connectable Advertising
2Mbps LE
LE Long Range

## Realtek RTL8852AE 802.11ax 2x2 Wi-Fi + BT5.2 (802.11ax 2x2, supporting gigabit data rate\*)

**NOTE\*** Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless LAN Standards	IEEE 002 112
WILETESS LAW STANDARDS	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k   IEEE 802.11r
	IEEE 802.111
Interoperability	Wi-Fi CERTIFIED™ modules
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
Data Rates	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz)
Modulation	Direct Sequence Spread Spectrum
Fiducation	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security <sup>3</sup>	• IEEE and Wi-Fi CERTIFIED™ 64 / 128 bit WEP encryption for a/b/g mode only
J. C. C. J. C. J. C.	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	OOE. I'A GGGGGGGGGGGGGGGGGGGGGGGGGGGGGGGGGGG



Technical Specifications – Networking and Communications

	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	WPA3 certification		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power <sup>2</sup>	• 802.11b: +18.5dBm minimum		
	• 802.11g: +17.5dBm minimum		
	• 802.11a: +18.5dBm minimum		
	• 802.11n HT20(2.4GHz): +15.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum		
	• 802.11n HT20(5GHz): +15.5dBm minimum		
	• 802.11n HT40(5GHz): +14.5dBm minimum		
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum		
	• 802.11ax HE40(2.4GHz) : +10dBm minimum		
	• 802.11ax HE80(5GHz): +10dBm minimum		
Power Consumption	• Transmit mode:2.5 W		
-	• Receive mode:2 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
	• Idle mode :50 mW (WLAN unassociated)		
	Connected Standby/Modern Standby: 10mW		
	Radio disabled: 8 mW		
Power Management	ACPI and PCI Express compliant power management		
<b>3</b>	802.11 compliant power saving mode		
Receiver Sensitivity <sup>3</sup>	• 802.11b, 1Mbps: -93.5dBm maximum		
	• 802.11b, 11Mbps: -84dBm maximum		
	• 802.11a/g, 6Mbps: -86dBm maximum		
	• 802.11a/g, 54Mbps: -72dBm maximum		
	• 802.11n, MCS07: -67dBm maximum		
	• 802.11n, MCS15: -64dBm maximum		
	, and the second		
	802.11ac, MCS0: -84dBm maximum     803.11ac, MCS0: 50dBm maximum		
	• 802.11ac, MCS9: -59dBm maximum		
	• 802.11ax, MCS11(HE40): -57dBm maximum		
	• 802.11ax, MCS11(HE80): -54dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8g		
	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C)		
	Non-operating -40° to 176° F (-40° to 80° C)		
Humidity	Operating 10% to 90% (non-condensing)		
	Non-operating 5% to 95% (non-condensing)		
Altitude	Operating 0 to 10,000 ft (3,048 m)		
	Non-operating 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON		



Technical Specifications – Networking and Communications

Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)		
	BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or		
	864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum		
	transmit power of +4 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW		
	Peak (Rx) 230 mW		
	Selective Suspend 17 mW		
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826		
	Low Voltage Directive IEC950		
	UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance		
	LE Link Layer Ping		
	LE Dual Mode LE Link Layer		
	LE Low Duty Cycle Directed Advertising		
	LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance		
	LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Extended Scanner Filter Policies		
	LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2 Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		
	BT5.1		
	ESR9/10 Compliance		
	LE Advertisement Extensions		
	Channel Selection Algo		
	Limited High Duty Cycle Non-Connectable Advertising		
	2Mbps LE		
	LE Long Range		





Technical Specifications – Input/Output Devices

### I/O DEVICES

HP Wired Desktop 320K K	eyboard			
Physical Characteristics	Keys	104, 105, 107, 109 layout (depending on country)		
	Dimensions (L x W x H)	16.77 x 4.36 x 0.65 in (426.2 x 110.9 x 16.7 mm)		
	Weight	14.57 oz (413g)		
	Cable length	6 ft. (1.8 m)		
Electrical	Operating voltage	5V		
	Power consumption	50mA - 100 mA		
	System interface	USB		
Mechanical	Keycaps	Low-profile design		
	Switch actuation	60±10g nominal peak force with tactile feedback		
	Switch life	10 million keystrokes (Life tester)		
	Switch type	Plunger		
Environmental				
	Operating temperature	50° to 122° F (10° to 50° C)		
	Non-operating temperature	-22° to 149° F (-30° to 65° C)		
	Operating humidity	10% to 90% (non-condensing at ambient)		
	Non-operating humidity	0% to 90% (non-condensing at ambient)		
Approvals	FCC, ICES, CULus, CE, GS, EAC, I	FCC, ICES, CULus, CE, GS, EAC, Ukraine, India BIS, KCC, RCM, BSMI, VCCI		
Ergonomic compliance	TUVGS	TUVGS		
Kit contents	Keyboard, QSP, Warranty Card	Keyboard, QSP, Warranty Card, Product Notice		

HP USB Premium Keyboard				
	Keys	104, 105 layout (depending upon country)		
Physical Characteristics	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)		
	Weight	1.54 lb. (698g)		
	Operating voltage	5 VDC, +/-5%		
	Power consumption	35mA (All LED on)		
Electrical	System interface	USB Type A plug connector		
Electricat	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV		
	EMI - RFI	Conforms to FCC rules for a Class B computing device		
	Microsoft® PC 99 - 2001	Functionally compliant		
Mechanical	Keycaps	Low-profile design		
rieciiaiiicat	Switch actuation	60±10g nominal peak force with tactile feedback		



### Technical Specifications – Input/Output Devices

	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft. (1.8 m)	
	Microsoft PC 99 - 2001	Mechanically compliant	
	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
Environmental	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, FCC, CE Mark, TUV GS, VCCI,	BSMI, RCM, KCC	
Ergonomic compliance	TUVGS		
Kit contents	Keyboard, QSP		
Warranty Card	Product Notice		

HP Wired Desktop 320M	Mouse			
Dimensions (H x L x W)	4.08 x 2.49 x 1.39 in (103.8	4.08 x 2.49 x 1.39 in (103.8 x 63.4 x 35.5 mm)		
Weight	2.67 oz (75.8 g)			
Mechanical	Connector	USB		
	Resolution	1000 DPI		
	Sensor Optical Red Sensor			
Tracking speed	Tracking acceleration 8G(max), 1G=9.8m/s2			
	Cable length	6 ft. (1.8 m)		
	Color	Jack Black		
Regulatory approvals	Compliant	FCC, ICES, CULus, CE, GS, EAC, Ukraine. India BIS, KCC, RCM, BSMI, VCCI		



Technical Specifications – Input/Output Devices

HP USB Premium Mouse			
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)		
Weight	0.19lb (90g)		
Environmental	Operating temperature	50° to 122°F (10° to 50° C)	
	Non-operating temperature	-22° to 140°F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	50 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2 g peak acceleration	
	Non-operating vibration	4 g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	12mA	
Mechanical	Connector	USB 2.0	
	Туре	3D mouse (3 keys and wheel)	
	Resolution	800, 1200, 1600 DPI	
	Sensor	Pixart PAN3606DL	
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2	
	Cable length	6 ft. (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	

HP USB Mouse				
Dimensions (H x L x W)	37mm x 115mm x 62.9mm	37mm x 115mm x 62.9mm		
Weight	90 +10g/- 5 g	90 +10g/- 5 g		
Color	Black	Black		
Connector	USB	USB		
Mashaniasi	Resolution	800 DPI sensitivity		
Mechanical	Buttons	Two primary buttons and clickable scroll wheel		



#### Technical Specifications – Audio/Multimedia

#### **AUDIO/MULTIMEDIA**

#### **HP EliteDesk 800 G8 Tower PC**

Type Integrated

HD Stereo Codec Realtek ALC3205

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP style headset and is re-taskable as a Line-in,

Line-out, Microphone-in or Headphone-out port

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

# of Channels on Line-Out Stereo (Left & Right channels)

#### **HP EliteDesk 800 G8 Small Form Factor PC**

Type Integrated
HD Stereo Codec Realtek ALC3205

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP style headset and is re-taskable as a Line-in,

Line-out, Microphone-in or Headphone-out port

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

# of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

#### HP EliteDesk 800 G8 Desktop Mini PC

Type Integrated
HD Stereo Codec Realtek ALC3205

Audio I/O Ports combo audio jack with CTIA and OMTP headset support

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

# of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



#### Technical Specifications – Audio/Multimedia

#### HP EliteOne 800 G8 24 & 27 All-in-One

**Bang & Olufsen Audio** 

Type Integrated

HD Stereo Codec Realtek ALC3274

Audio I/O Ports Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port All ports are 3.5mm and support stereo

Internal Speaker Amplifier 5W per channel class D stereo amplifier for the internal speakers only

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speakers.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

# of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes - Stereo

Technical Specifications – Integrated Webcam and Microphone

#### INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Full HD RGB webcam & microphone; maximum resolution of 2592 x 1944 Optional integrated 5 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of  $2592 \times 1944$ 

**NOTE:** All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

#### INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch

Fingerprint matching: Performed on device

Anti-Spoofing: Yes

Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No





#### Technical Specifications – Power

#### **POWER**

#### **HP EliteDesk 800 G8 Tower PC**

#### **Unit Environment and Operating Conditions**

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

#### **HP EliteDesk 800 G8 SFF PC**

#### **Unit Environment and Operating Conditions**

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

#### HP EliteDesk 800 G8 Desktop Mini PC (35W)

#### **Unit Environment and Operating Conditions**

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

#### HP EliteDesk 800 G8 Desktop Mini (65W)

### **Unit Environment and Operating Conditions**

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)



Technical Specifications – Power

#### HP EliteOne 800 G8 24 & 27 All-in-One

#### **Unit Environment and Operating Conditions**

Temperature Range Operating: 5°C ~45°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 120W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 180W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	N/A	N/A
80 PLUS Platinum	N/A	260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	550W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	210W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current				
Rated Input Current with Energy Efficient* Power Supply	90W≦1.7A 120W≦1.7A 180W≦2.5A	260W Platinum≦3.1A 350W Platinum≦4A	260W Platinum≤3.1A 350W Platinum≤4A 550W Platinum≤6.6A	210W ≦2.8A
DC Output	+19.5V	+12V	+12V	+20V



Technical Specifications – Power

	DM	SFF	TWR	AiO
Current Leakage (NFPA 99: 2012)	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in	disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances	patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Power Adapter	External power	Internal power	Internal power supply	Internal power supply
Dimensions	90W: 127mm x 51mm x 30mm 120W: 138mm x 68.5mm x 25.4mm 180W: 165.5mm x 79mm x 25.4mm	165mm x 95mm x 73mm	165mm x 95mm x 73mm	110x110x26mm
Total Cord Length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)



### Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions: Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated	-	85%	88%	90%	92%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ





Technical Specifications – Weights and Dimensions

#### **WEIGHTS & DIMENSIONS**

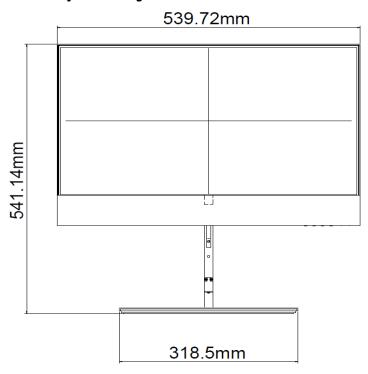
	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34 mm	13.3 x 12.13 x 3.94 in 338 x 308 x 100 mm	6.61 x 12.13 x 14.57 in 168 x 308 x 370 mm	See table below.
System Volume	63.4 cu in 1.05L	63.4 cu in 10.4 L	1168 cu in 19.14 L	See table below.
System Weight	3.13 lb 1.42 kg	13.5 lb 6.13 kg	13.11 lb 5.95 kg	See table below.
Max Supported Weight (desktop orientation)	0 1	77 lb 35 kg	77 lb 35 kg	See table below.
<b>Stand Dimensions</b>	160 x 117 x 18.5 mm	151.8 x 200 x 37.2mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 5.2 x 9.3 in 498 x132 x 235 mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm	11.77 x 18.82 x 20.35 in 299 x 478 x 517 mm	See table below.
Shipping Weight	2.95 kg 6.49 lb	9 kg 19.82 lb	11.34 kg 24.98 lb	See table below.
Multipack Packaging (10 units)	20.28 x16.54 x 25 in 515 x 420 x 636 mm			
Palletization Profile	10-units per layer 10 layers max 100 units per pallet 46.3 x 39.2 x 57.7 in, 1175 x 996 x 2125 mm (include pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	8 units per layer 4 layers ax 32 units per pallet 1200 x 1000 x 2203 mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm

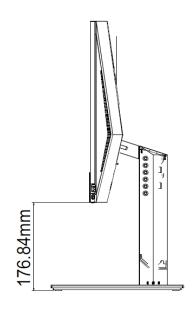


Technical Specifications – Weights and Dimensions

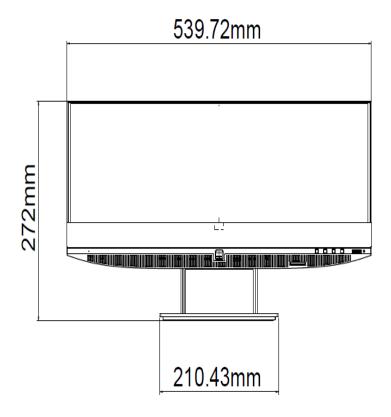
#### STANDS AND DIMENSIONS

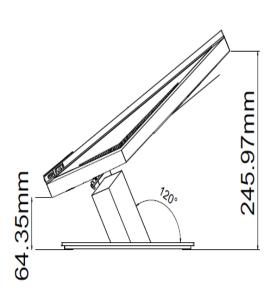
HP EliteOne G6 AIO Adjustable Height Stand - 23.8"





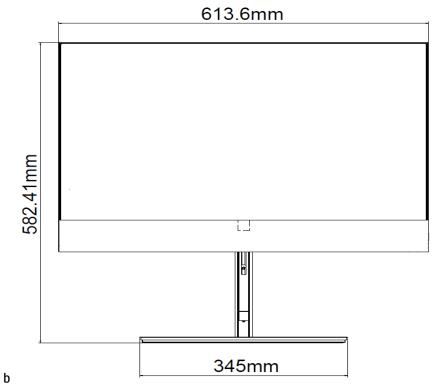
HP EliteOne G6 AIO Recline Stand - 23.8"

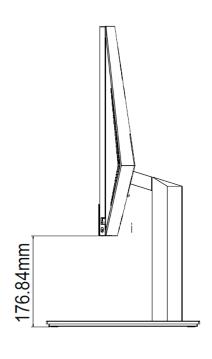




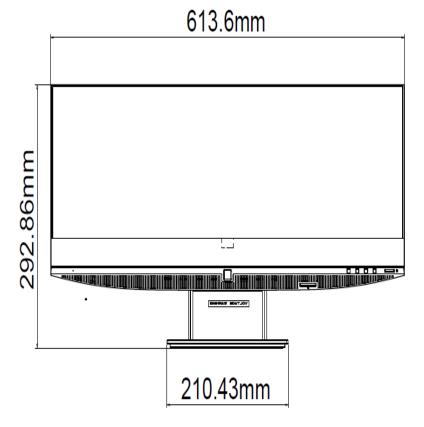
Technical Specifications – Weights and Dimensions

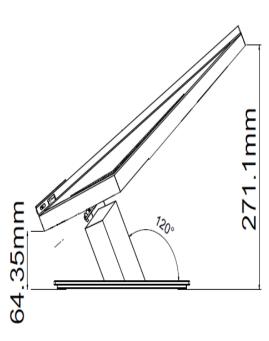
#### HP EliteOne G6 AIO Adjustable Height Stand - 27"





HP EliteOne G6 AIO Recline Stand - 27"





### Technical Specifications – Weights and Dimensions

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)	
	Portrait Adjustment	No portrait	
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait	
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)	
	Pivot	No pivot	

Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel





Technical Specifications – Weights and Dimensions

#### **ALL-IN-ONE WEIGHTS AND DIMENSIONS**

#### Weight without Touch Panel - 23.8"

Product Weight Unboxed	15.12 lbs. 6.86 kg	Stand	Recline Stand 18.83 lbs. 8.54 Kg
Shipping Weight Boxed	19.51 lbs.	Stand	Recline Stand 23.08 lbs. 10.47 kg
Shipping Weight Pallet (30 units)	623.7 lbs.	Stand	Recline Stand 730.62 lbs. 332.1 kg

### Weight with Touch Panel - 23.8"

Product Weight Unboxed	Without Stand 17.50 lbs. 7.94 kg	Adjustable Height Stand 22.84 lbs. 10.36 kg	Recline Stand 21.21 lbs. 9.62 Kg
Shipping Weight Boxed	Without Stand 21.89 lbs. 9.93 kg	Adjustable Height Stand 27.23 lbs. 12.35kg	Recline Stand 25.46 lbs. 11.55 kg
Shipping Weight Pallet (30 units)	Without Stand 694.98 lbs. 315.9 kg	Adjustable Height Stand 854.7lbs. 388.5kg	Recline Stand 801.9lbs. 364.5 kg

#### Dimensions (W $\times$ D $\times$ H) – 23.8"

Product Dimensions	Without Stand 539.72 x 364.3 x 57.3 mm		Recline Stand Stand (30 ~ 60) degrees
(Non-touch)		539.72 x 541.14 x 236.98 mm	539.72 x 379.44 x 209.35 mm
Product	Without Stand	Adjustable Height	Recline Stand
Dimensions	539.72 x 364.3 x 59.3 mm	Stand (-5 ~ 20) degrees	Stand (30 ~ 60) degrees
(In-cell Touch)		539.72 x 541.14 x 236.98 mm	539.72 x 379.44 x 211.35 mm

#### Shipping Dimensions - 23.8"

- 11 3	11		Recline Stand 628 x 186 x 635 mm
Shipping	Without Stand	Adjustable Height	Recline Stand
Dimensions	1180 x 874 x 2060 mm	1180 x 874 x 2060 mm	1180 x 874 x 2060 mm
Pallet			
Pallet (40 units)			



Technical Specifications – Weights and Dimensions

### Weight without Touch Panel - 27"

Product Weight Unboxed	Without Stand 17.79 lbs. 8.07 kg	Adjustable Height Stand 23.63 lbs. 10.72 kg	Recline Stand 21.50 lbs. 9.75 Kg
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Stand 27.40 lbs. 12.43 kg
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg

### Shipping Dimensions – 27"

- 11 3	742 x 237 x 640 mm	-,	Recline Stand 742 x 237 x 640 mm
			Recline Stand 1180 x 958 x 2076 mm



Technical Specifications – Miscellaneous Features

#### MISCELLANEOUS FEATURES

#### **Management Features**

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
   Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

#### **Serviceability Features**

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
    - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
    - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
    - 2 red + 4 white BIOS recovery is in progress
    - 3 red + 2 white Memory could not be initialized
    - 3 red + 3 white Graphics adaptor could not be found
    - 3 red + 4 white Power supply failure / not connected
    - 3 red + 5 white Processor not installed
    - 3 red + 6 white Current processor does not support an enabled feature
    - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
    - 4 red + 3 white System internal temperature has exceeded its threshold
    - 5 red + 2 white System controller firmware is not valid
    - 5 red + 3 white System controller detected BIOS is not executing
    - 5 red + 4 white BIOS could not complete initialization / PCA failure
    - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
  - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- 1 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only. SFF/DM requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

Technical Specifications – After Market Options

#### **AFTER MARKET OPTIONS**

Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
AMD® Radeon™ RX 550X 4GB Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	Х		5JW82AA
AMD® Radeon™ R7 430 2GB DP+VGA Card		Х	Х		5JW81AA

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	<u>MT</u>	<u>Ai0</u>	Part Number
HP Desktop Mini Port Cover v3	<u>X</u> (95W and discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	<u>X</u> (95W and discrete GPU skus not supported)				13L70AA
HP Desktop Mini 90W Power Supply Kit	<u>X</u>				L4R65AA
HP Desktop Mini Lock Box V2	<u>X</u> (95W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	X (Either one)				K9Q83AA
HP Desktop Mini Security/Dual VESA Sleeve v3	<u>X</u> (95W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	<u><b>X</b></u> (95W and discrete GPU skus not supported)				13L68AA
HP B250 PC Mounting Bracket	<u>X</u>				<u>8RA46AA</u>
HP B300 PC Mounting Bracket	<u>x</u>				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	<u>X</u> (95W and discrete GPU skus not supported)				<u>7DB37AA</u>
HP B500 PC Mounting Bracket	<u>X</u>				<u>2DW52AA</u>
HP Desktop Mini Vertical Chassis Stand	<u>X</u>				<u>G1K23AA</u>
HP DM Power Supply Holder Kit v2	(95W and discrete GPU skus not supported)				<u>7DB38AA</u>
HP Quick Release Bracket 2	<u>X</u>			<u>x</u>	<u>6KD15AA</u>
HP Single Monitor Arm	<u>X</u>			<u>x</u>	<u>BT861AA</u>

Data Storage Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
HP PCIe NVME TLC M.2 256GB SSD	X	X	Х	Х	1CA51AA
HP PCIe NVME TLC M.2 512GB SSD	X	X	Х	Х	X8U75AA
HP PCIe Gen 4 NVME TLC M.2 512GB SSD	X	X	Х		406L8AA
HP PCIe Gen 4 NVME TLC M.2 1TB SSD	X	Х	Х		406L7AA
HP 500GB 7200PRM SATA 3.5" Hard Drive		х	X		QK554AA



### Technical Specifications – After Market Options

HP 1TB 7200rpm SATA 3.5" Hard Drive	Х	X	QK555AA
HP 9.5mm Tower DVD-Writer	Х	X	1CA52AA

Input Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u> <u>Number</u>
HP Desktop Wired 320K Keyboard	X	Х	Х	Х	9SR37AA
HP 125 Wired Keyboard	X	Х	Х	Х	266C9AA
HP 225 Antimicrobial Wired Mouse and Keyboard Combo	X	Х	Х	Х	286K3AA
HP 225 Wired Mouse and Keyboard Combo	X	Х	Х	Х	286J4AA
HP 125 Wired Mouse	X	Х	Х	Х	265A9AA
HP 128 Laser Wired Mouse	X	Х	Х	Х	265D9AA
HP Wired Desktop 320K Keyboard	X	Х	X	Х	9SR37AA
HP Wired Desktop 320M Mouse	X	Х	Х	Х	9VA80AA
HP Wired Desktop 320MK Mouse and Keyboard	X	Х	X	Х	9SR36AA
HP USB Business Slim CCID SmartCard Keyboard	X	Х	Х	Х	Z9H48AA
HP USB Keyboard and Mouse Healthcare Edition	X	Х	X	Х	1VD81AA
HP USB Premium Keyboard	X	Х	X	Х	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	Х	Х	Х	BU207AA
HP Wireless Business Slim Keyboard and Mouse	X	Х	X	Х	T6L04AA
HP Wireless Premium Keyboard	X	Х	Х	Х	Z9N41AA
HP PS/2 Business Slim Keyboard		Х	X		N3R86AA
HP USB Fingerprint Mouse	X	Х	Х	Х	4TS44AA
HP USB Premium Mouse	X	Х	Х	Х	1JR32AA
HP PS/2 Mouse		Х	Х		QY775AA
HP Wireless Premium Mouse	Х	Х	Х	Х	1JR31AA

#### 1. Not available in all regions

System Memory	<u>DM</u>	SFF	TWR	AiO	<u>Part</u> <u>Number</u>
HP 4GB DDR4-3200 UDIMM		Х	X		13L78AA
HP 8GB DDR4-3200 UDIMM		Х	X		13L76AA
HP 16GB DDR4-3200 UDIMM		Х	X		13L74AA
HP 32GB DDR4-3200 UDIMM		Х	X		13L72AA
HP 4GB DDR4-3200 SODIMM	X			X	13L79AA
HP 8GB DDR4-3200 SODIMM	X			X	13L77AA
HP 16GB DDR4-3200 SODIMM	X			X	13L75AA
HP 32GB DDR4-3200 SODIMM	X			Х	13L73AA



Technical Specifications – After Market Options

Multimedia Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business Headset v2	X	Х	Х	X	T4E61AA
HP S101 Speaker Bar	Х	Х	Х		5UU40AA

Security Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business PC Security Lock v3 Kit		Х	Х	Х	3XJ17AA
HP Dual Head Keyed Cable Lock		Х	Х	Х	T1A64AA
HP Keyed Cable Lock 10mm	Х	Х	Х	Х	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	Х	X	X	T1A63AA

Stands and Accessories	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP EliteOne 800 G6 23.8" Height Adjustable Stand				х	13L61AA
HP EliteOne 800 G6 23.8" Recline Stand				X	13L62AA
HP EliteOne 800 G6 27" Height Adjustable Stand				X	13L63AA
HP EliteOne 800 G6 27" Recline Stand				X	13L64AA

I/O Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part Number</u>
HP DisplayPort Port Flex IO v2	X	Х	Х		13L54AA
HP Type-C <sup>®</sup> USB 3.1 Gen2 Port Flex IO v2		Х	Х		<u>13L59AA</u>
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	х	х		13L58AA
HP VGA Port Flex IO v2	Х	Х	Х		<u>13L53AA</u>
HP Serial Port Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	х	х		<u>13L56AA</u>
HP Serial Port Flex IO 2 <sup>nd</sup> v2	X (Not Available on 95W and discrete GPU SKUs)				<u>13L57AA</u>
HP Internal Serial Port (in rear wall)		Х	X		3TK82AA
HP PCIe x1 Parallel Port Card		Х	X		N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		Х	X		1VD82AA
HP USB to Serial Port Adapter	Х	Х	X		J7B60AA
HP USB-C to Display Port Adapter	Х	X	X		N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)				2MY05AA
HP HDMI Standard Cable Kit	Х	Х	X		<u>T6F94AA</u>
HP DisplayPort Cable Kit	Х	Х	X		<u>VN567AA</u>
HP DisplayPort To VGA Adapter	X	Х	Х		AS615AA



### HP EliteDesk 800 G8 and HP EliteOne 800 G8 Desktops PCs

## QuickSpecs

Technical Specifications – After Market Options

HP DisplayPort To DVI-D Adapter	X	X	X	FH973AA

**NOTE:** For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
Intel® Ethernet I225-T1 GbE NIC		X	X		<u>TBD</u>
Intel Wi-Fi 6 AX200 ax 2x2 + BT5 non- vPro		Х	Х		

Intel® Optane Memory	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part Number</u>
512GB Intel® Optane™ Memory H10 with SSD	х	х	х	Х	6VF55AA



### HP EliteDesk 800 G8 and HP EliteOne 800 G8 Desktops PCs

### QuickSpecs

### Change Log

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Date	Version History	Action	Description of Change	
	From v1 to v2			
	From v2 to v3			
	From v3 to v4			
	From v4 to v5			
	From v5 to v6			
	From v6 to v7			
	From v6 to v7			
	From v8 to v9			
	From v9 to v10			

